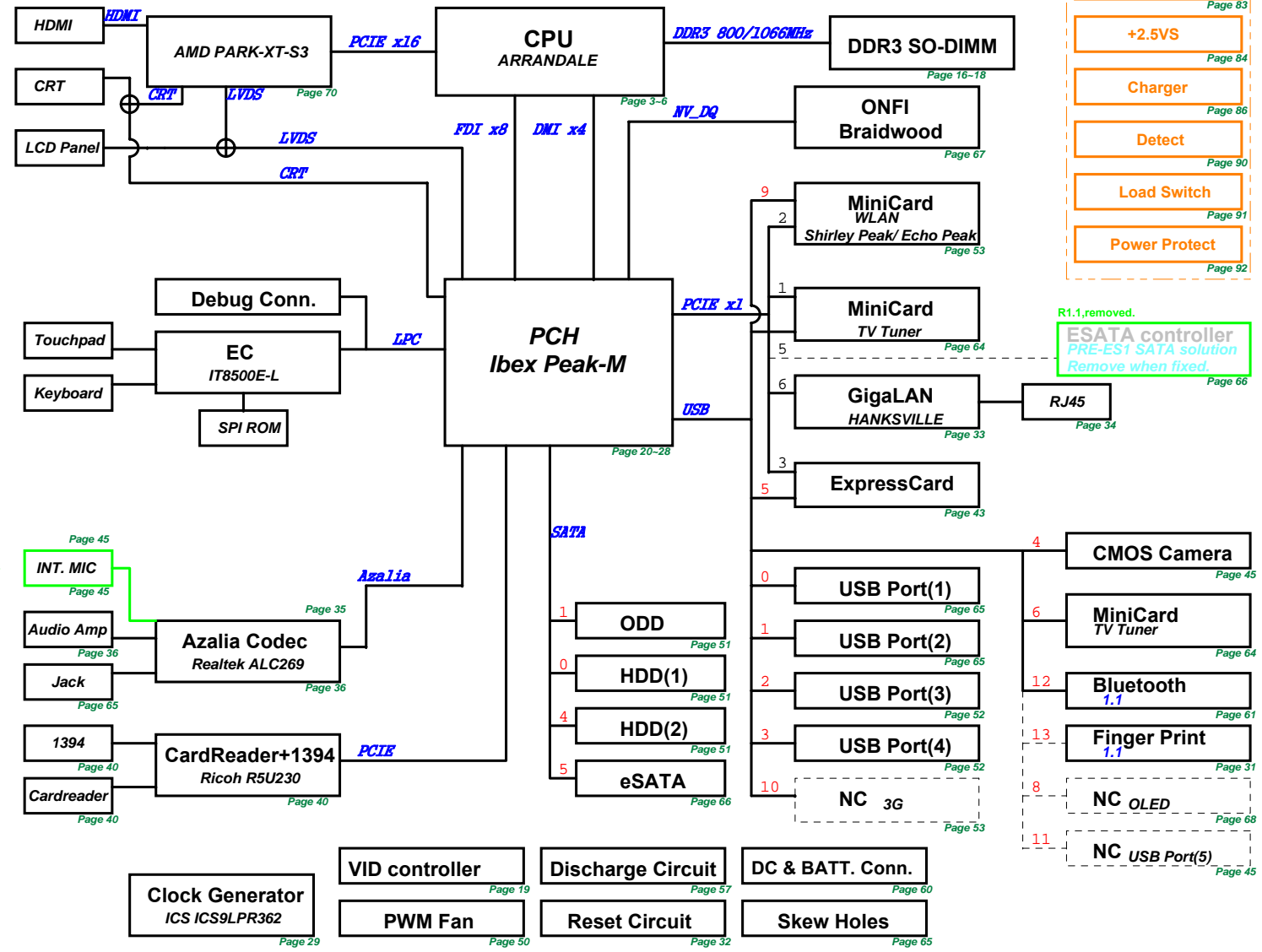


K42F SCHEMATIC For BOM Rev1.0

- 01_Block Diagram
- 02_System Setting
- 03_CPU(1)_DMI, PEG, FDI, CLK, MISC
- 04_CPU(2)_DDR3
- 05_CPU(3)_CFG, GND, Thermal Diode
- 06_CPU(4)_PWR
- 07_CPU(5)_XDP
- 08_DDR3 SO-DIMM_0
- 09_DDR3 SO-DIMM_1
- 10_PCH_SFI_ROM
- 11_PCH_STRAP
- 12_PCH_IBEX(1)_SATA, IHDA, RTC, LPC
- 13_PCH_IBEX(2)_PCIe, CLK, SMB, PEG
- 14_PCH_IBEX(3)_FDI, DMI, SYS PWR
- 15_PCH_IBEX(4)_DP, LVDS, CRT
- 16_PCH_IBEX(5)_PCI, NVRAM, USB
- 17_PCH_IBEX(6)_CPU, GPIO, MISC
- 18_PCH_IBEX(7)_POWER
- 19_PCH_IBEX(8)_POWER
- 20_PCH_IBEX(9)_GND
- 21_CLOCK_GEN-ICS9LPRS427C
- 22_EC_IT8500
- 23_TP_KB
- 24_Forceoff#_FWRGD_Thermal
- 25_FAN_Thermalsensor
- 26_AUD-ALC269
- 27_AUD-HEADPHONE & SPEAKER
- 28_LAN-JMC251_LAN&Cardreader
- 29_LVDS_SW
- 30_BUG_Debug
- 31_LVDS & INVERTER CONNECTOR
- 32_CRT_CON
- 33_CRT_SW
- 34_HDMI_CON
- 35_HDMI_DRIVE (K32F)
- 36_FAN (EMPTY)
- 37_XDD_HDD & ODD
- 38_USB_USB Port *2
- 39_BOARD_TO_BOARD_CON
- 40_LED_Indicator
- 41_DSG_Discharge
- 42_BAT_Conn.
- 43_BT_Bluetooth&CAMERA
- 44_ME_Conn & Skew Hole
- 45_EMI
- 46_power Flow
- 47.Power System (8206)
- 48.Power_VTT_CPU
- 49.Power_t1_8VS
- 50.Power_load switch
- 51.Power_for test
- 52.Power_vcore
- 53.Power_charge
- 54.Power_t1_5V#10.75VS
- 55.Power_WGFX_CORE
- 56.Power Control
- 57.Power On Sequence
- 58.Power On Timing--AC mode
- 59.Power On Timing--DC mode

BLOCK DIAGRAM



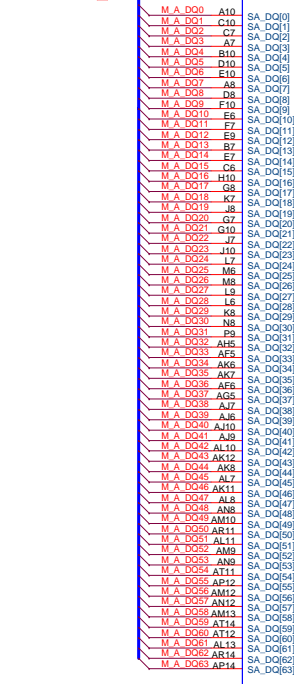
Power

- VCORE Page 80
- System Page 81
- 1.5VS & 1.05VS Page 82
- DDR & VTT Page 83
- +2.5VS Page 84
- Charger Page 86
- Detect Page 90
- Load Switch Page 91
- Power Protect Page 92

R1.1, removed.
ESATA controller
 PRE-ES1 SATA solution
 Remove when fixed.

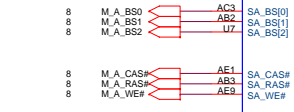
U301C

8 M_A_DQ[63:0]



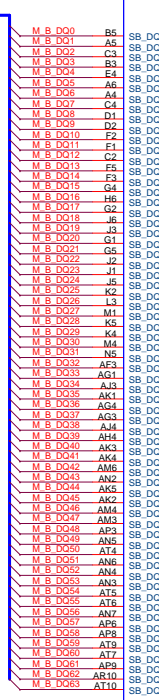
DDR SYSTEM MEMORY A

SOCKET989



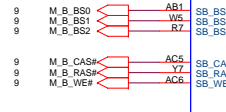
U301D

9 M_B_DQ[63:0]

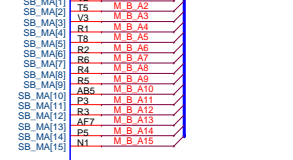
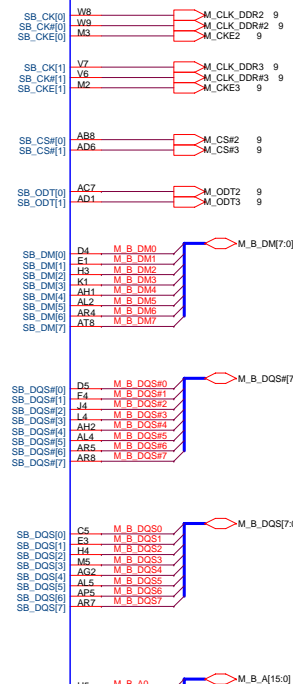


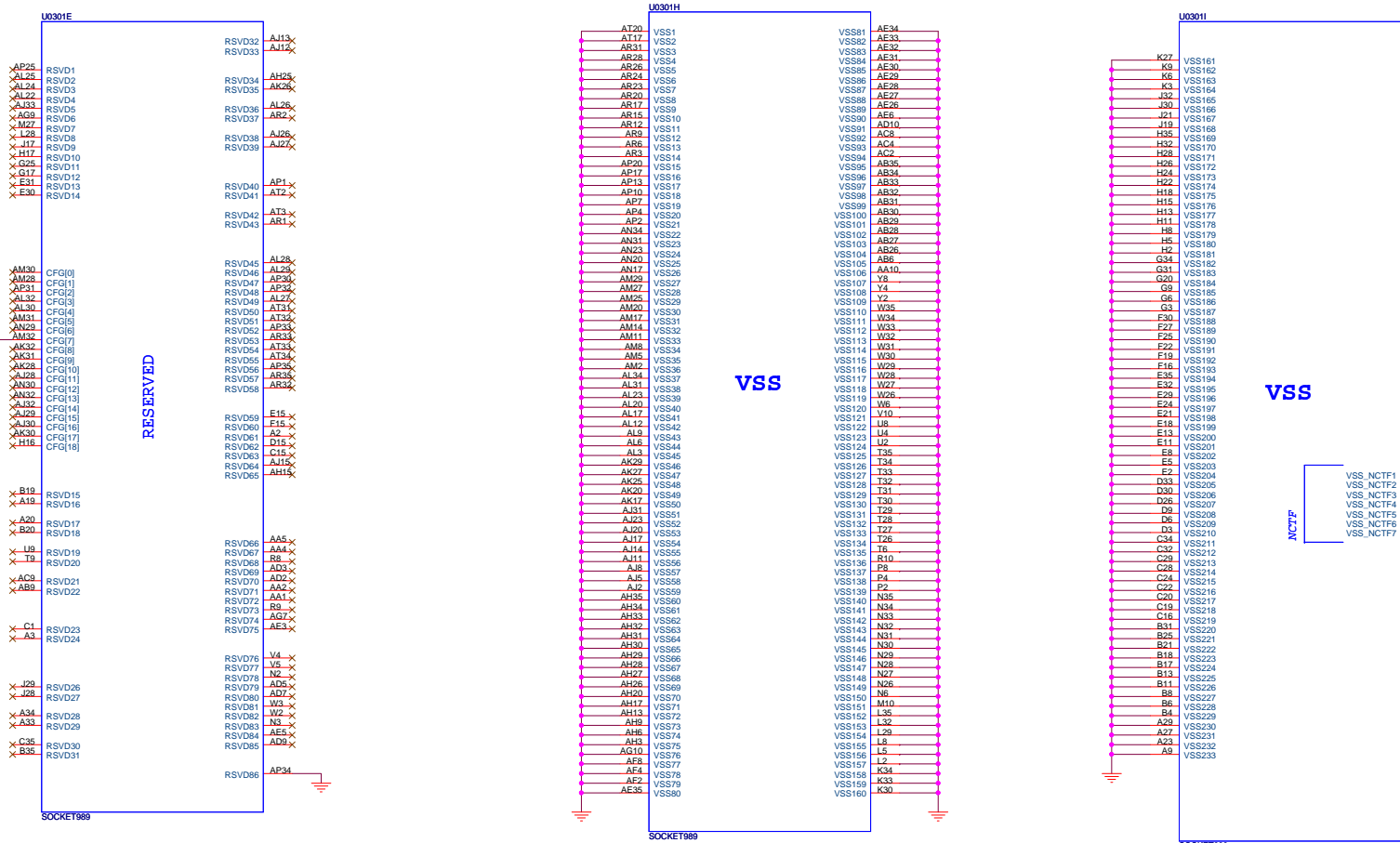
DDR SYSTEM MEMORY - B

SOCKET989



9 M_B_DQ[63:0]





CFG strapping information:

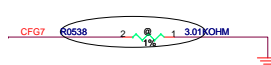
CFG[1:0]: PCI Express Port Bifurcation:(Clarksfield Only)
 - 11 = 1 x 16 PEG (Default)
 - 10 = 2 x 8 PEG

CFG[3]: PCIe Static Numbering Lane Reversal.(Arrandale Only)
 - 1: Normal Operation (Default)
 - 0: Lane Numbers Reversed 15 -> 0, 14 -> 1, ...

CFG[4]: Embedded DisplayPort Detection.(Arrandale Only)
 - 1: Disabled - No Physical Display Port attached to Embedded DisplayPort
 - 0: Enabled - An external Display Port device is connected to the Embedded DisplayPort

CFG[7]: Fixed for PCI Express 2.0 (later specifications) (Clarksfield)
 Clarksfield (only for early samples pre-E53) - Connected to GND with 3.01K Ohm/5% resistor for a common motherboard design (for AUB and CFD), the pull-down resistor should be used. Does not impact Arrandale functionality.
Unmount if Intel has fixed this issue.

Note: (Auburndale)Hardware Straps are sampled on the asserting edge of VCCPWRGOOD_0 and VCCPWRGOOD_1 and latched inside the processor.
 Note: (Clarksfield)Hardware Straps are sampled after RSTIN# de-assertion.



CFG strapping information:

For Arrandale

CFG[2:0] - Reserved configuration pins. Test points may be placed on these pins on a common motherboard design.

CFG[3] - PCI Express* Static Lane Numbering Reversal. Lane Reversal will be applied across all 16 Lanes.

- 1: No lane reversal
- 0: Reversal

CFG[4] - Embedded DisplayPort Detection: This is used to detect the presence of a device on the Embedded DisplayPort.

CFG[17:5] - Reserved configuration pins.

Note: Hardware straps are sampled on the asserting edge of VCCPWRGOOD_0 and VCCPWRGOOD_1 and latched inside the processor.

For Clarksfield

CFG[1:0] - PCI Express* Port Bifurcation:

- 11 = 1 x16 PEG
- 10 = 2 x8 PEG

CFG[2] - Reserved Configuration pin.

CFG[3] - Reserved (Used by Arrandale Pprocessors for PCI Express* Static Lane Numbering Reversal)

CFG[11:4] - Reserved configuration pins.

CFG[12] - N/A on Clarksfield processors.

CFG[17:13] - Reserved configuration pins.

Note: Hardware straps are sampled after RSTIN# de-assertion.

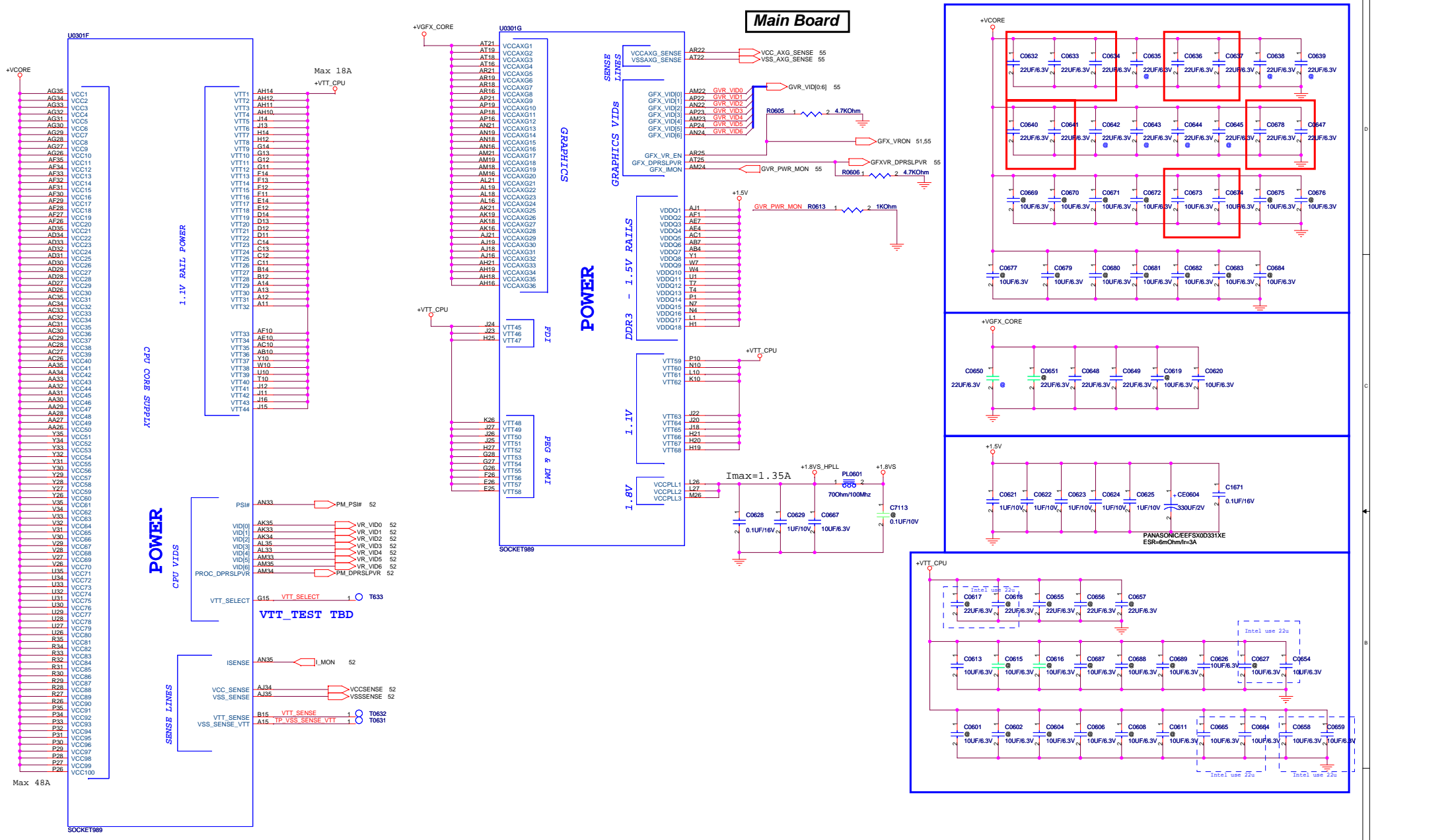
ASUS Title : CPU(3)_CFG.RSV.D.GND
 Engineer: Modim Zhang

ASUSTeK COMPUTER INC. NBI

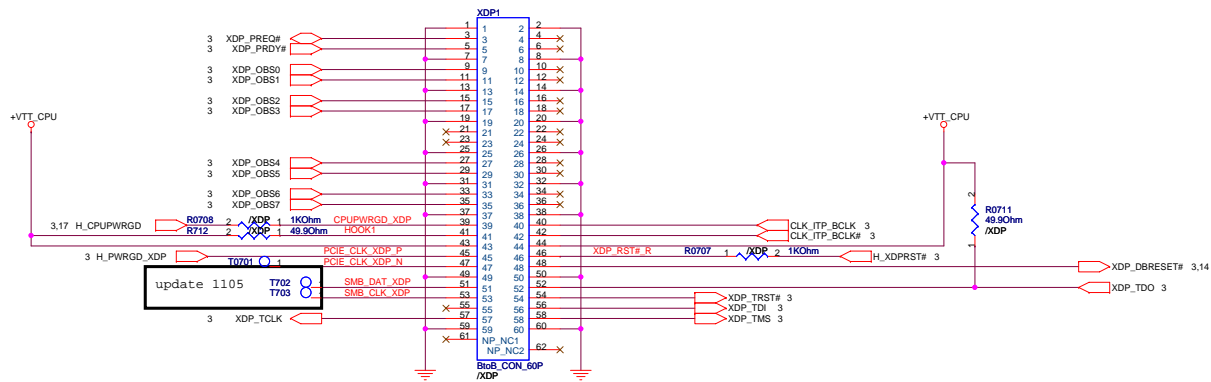
Size C Project Name K42F Rev 1.0

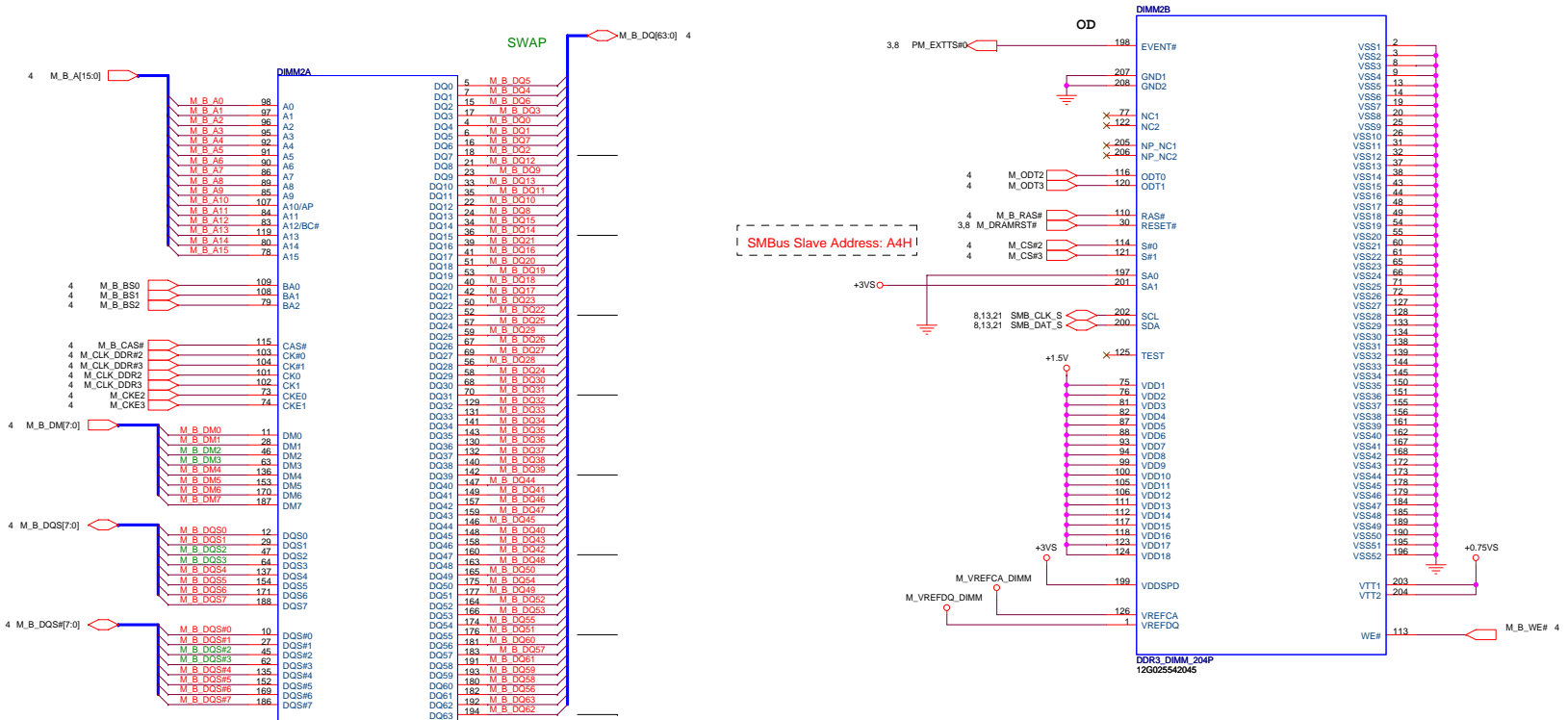
Date: Tuesday, November 10, 2009 Sheet 5 of 59

Main Board

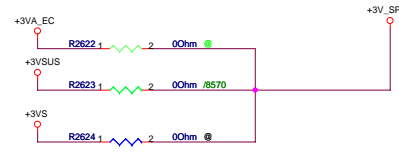


CPU XDP connector





PCH SPI ROM



PCH SPI ROM

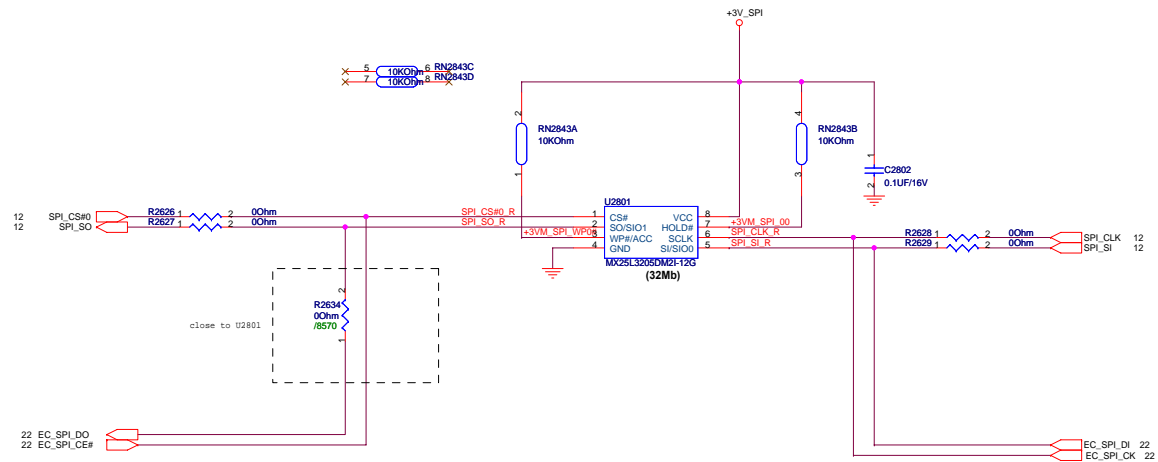


Table 2-28. Functional Strap Definitions (Sheet 1 of 5)

Signal	Usage	When Sampled	Comment
SPKR	No Reboot	Rising edge of PWROK	The signal has a weak internal pull-down. Note: the internal pull-down is disabled after PLTRST# de-asserts. If the signal is sampled high, this indicates that the system is strapped to the "No Reboot" mode (the PCH will disable the TCO Timer system reboot feature). The status of this strap is readable using the NO REBOOT bit (Chipset Config Registers: Offset 3410h:bit 5).
INT3_3V#	Reserved	Rising edge of PWROK	This signal has a weak internal pull-up. Note: the internal pull-up is disabled after PLTRST# de-asserts. NOTE: This signal should not be pulled low.
GNT[3]# / GPIO[55]	Top-Block Swap Override	Rising edge of PWROK	The signal has a weak internal pull-up. Note: the internal pull-up is disabled after PCIRST# de-asserts. If the signal is sampled low, this indicates that the system is strapped to the "topblock swap" mode (the PCH inverts A16 for all cycles targeting BIOS space). The status of this strap is readable using the Top Swap bit (Chipset Config Registers: Offset 3414h:bit 0). Note that software will not be able to clear the Top-Swap bit until the system is rebooted without GNT3# being pulled down.
INTVRMEN	Integrated 1.05 V VRM Enable / Disable	Always	Integrated 1.05 V VRMs is enabled when high. NOTE: This signal should always be pulled high.

Table 2-28. Functional Strap Definitions (Sheet 2 of 5)

Signal	Usage	When Sampled	Comment															
GNT1# / GPIO1	Boot BIOS Strap bit [1] BBS[1]	Rising edge of PWROK	This signal has a weak internal pull-up. Note that the internal pull-up is disabled after PCIRST# de-asserts. This field determines the destination of accesses to the BIOS memory range. Also, controllable using Boot BIOS Destination bit (Chipset Config Registers: Offset 3410h:bit 1). This strap is used in conjunction with Boot BIOS Destination Selection 0 strap. <table border="1"> <thead> <tr> <th>Bit11</th> <th>Bit 10</th> <th>Boot BIOS Destination</th> </tr> </thead> <tbody> <tr> <td>0</td> <td>1</td> <td>Reserved</td> </tr> <tr> <td>1</td> <td>0</td> <td>PCI</td> </tr> <tr> <td>1</td> <td>1</td> <td>SPI</td> </tr> <tr> <td>0</td> <td>0</td> <td>LPC</td> </tr> </tbody> </table> NOTE: If option 00 LPC is selected, BIOS may still be placed on LPC, however, all platforms with the PCH require SPI flash connected directly to the PCH SPI bus with a valid descriptor in order to boot. NOTE: Booting to PCI is intended for debug/testing only. Boot BIOS Destination Select to LPC/PCI by functional strap or using Boot BIOS Destination Bit will not affect SPI accesses initiated by Intel® Management Engine or Integrated GbE LAN.	Bit11	Bit 10	Boot BIOS Destination	0	1	Reserved	1	0	PCI	1	1	SPI	0	0	LPC
Bit11	Bit 10	Boot BIOS Destination																
0	1	Reserved																
1	0	PCI																
1	1	SPI																
0	0	LPC																

Table 2-28. Functional Strap Definitions (Sheet 5 of 5)

Signal	Usage	When Sampled	Comment
SDVO_CTRLDATA	Digital Display Port (Port B)	Rising Edge of PWROK	This signal has a weak internal pull-down. Note that the weak internal pull-down is disabled after PLTRST# de-asserts. Port B is enabled when sampled high. When sampled low Port B is Disabled.
DDPC_CTRLDATA	Digital Display Port (Port C)	Rising Edge of PWROK	This signal has a weak internal pull-down. Note that the weak internal pull-down is disabled after PLTRST# de-asserts. Port C is enabled when sampled high. When sampled low Port C is Disabled.
DDPD_CTRLDATA	Digital Display Port (Port D)	Rising Edge of PWROK	This signal has a weak internal pull-down. Note that the weak internal pull-down is disabled after PLTRST# de-asserts. Port D is enabled when sampled high. When sampled low Port D is Disabled.

Table 2-28. Functional Strap Definitions (Sheet 3 of 5)

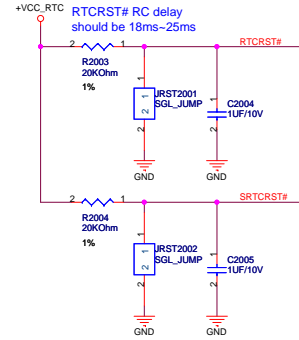
Signal	Usage	When Sampled	Comment															
GNT[0]#	Boot BIOS Strap bit[0] BBS[0]	Rising edge of PWROK	This Signal has a weak internal pull-up. Note that the internal pull-up is disabled after PCIRST# de-asserts. This field determines the destination of accesses to the BIOS memory range. Also, controllable using Boot BIOS Destination bit (Chipset Config Registers: Offset 3410h:bit 10). This strap is used in conjunction with Boot BIOS Destination Selection 1 strap. <table border="1"> <thead> <tr> <th>Bit11</th> <th>Bit 10</th> <th>Boot BIOS Destination</th> </tr> </thead> <tbody> <tr> <td>0</td> <td>1</td> <td>Reserved</td> </tr> <tr> <td>1</td> <td>0</td> <td>PCI</td> </tr> <tr> <td>1</td> <td>1</td> <td>SPI</td> </tr> <tr> <td>0</td> <td>0</td> <td>LPC</td> </tr> </tbody> </table> NOTE: If option 00 LPC is selected, BIOS may still be placed on LPC, however, all platforms with the PCH require SPI flash connected directly to the PCH's SPI bus with a valid descriptor in order to boot. NOTE: Booting to PCI is intended for debug/testing only. Boot BIOS Destination Select to LPC/PCI by functional strap or using Boot BIOS Destination Bit will not affect SPI accesses initiated by Management Engine or Integrated GbE LAN.	Bit11	Bit 10	Boot BIOS Destination	0	1	Reserved	1	0	PCI	1	1	SPI	0	0	LPC
Bit11	Bit 10	Boot BIOS Destination																
0	1	Reserved																
1	0	PCI																
1	1	SPI																
0	0	LPC																
GNT2# / GPIO53	ESI Strap (Server Only)	Rising edge of PWROK	This Signal has a weak internal pull-up. Note that the internal pull-up is disabled after PCIRST# de-asserts. Tying this strap low configures DMI for ESI compatible operation. NOTE: ESI compatible mode is for server platforms only. This signal should not be pulled low for desktop and mobile.															
NV_ALE	Reserved	Rising edge of PWROK	This signal has a weak internal pull-down. NOTE: This signal should not be pulled high.															

Table 2-28. Functional Strap Definitions (Sheet 4 of 5)

Signal	Usage	When Sampled	Comment
HDA_DOCK_EN# / GPIO[33]	Flash Descriptor Security Override/ ME Debug Mode	Rising edge of PWROK	Signal has a weak internal pull-up. If strap is sampled high, the security measures defined in the Flash Descriptor will be in effect (default). If sampled low, the Flash Descriptor Security will be overridden. This strap should only be asserted low using external pull down in manufacturing/debug environments ONLY. NOTE: Asserting the GPIO33 low on the rising edge of PWROK will also halt Intel® Management Engine after chipset bringup and disable runtime Intel® Management Engine features. This is a debug mode and must not be asserted after manufacturing/debug.
SPI_MOSI	TPM Functionality Disable	Rising edge of MEPWROK	This signal has a weak internal pull-down resistor. This signal must be sampled low.
NV_CLE	DMI Termination Voltage	Rising edge of PWROK	This signal has a weak internal pull-down.
HDA_SDO	Reserved	Rising edge of RSMRST#	This signal has a weak internal pull down. NOTE: This signal should not be pulled high.
GPIO8	Reserved	Rising edge of RSMRST#	This signal has a weak internal pull up. Note that the weak internal pull-up is disabled after RSMRST# de-asserts. NOTE: This signal should not be pulled low.
GPIO27	Reserved	Rising edge of RSMRST# pin	This signal should be left as a No Connect.
HDA_SYHC	On-Die PLL Voltage Regulator Voltage Select	Rising edge of RSMRST# pin	This signal has a weak internal pull down. On-Die PLL VR is supplied by 1.5 V when sampled high; 1.8 V when sampled low.
GPIO15	Reserved	Rising edge of RSMRST# pin	Low = Intel® Management Engine Crypto Transport Layer Security (TLS) cipher suite with no confidentiality High = Intel® Management Engine Crypto TLS cipher suite with confidentiality This signal has a weak internal pull down. NOTE: A strong pull up may be needed for GPIO functionality.
L_DDC_DATA	LVDS	Rising Edge of PWROK	This signal has a weak internal pull-down. Note that the weak internal pull-down is disabled after PLTRST# de-asserts. LVDS is enabled when sampled high. When sampled low LVDS is Disabled.

Request by CSC for CMOS clear function

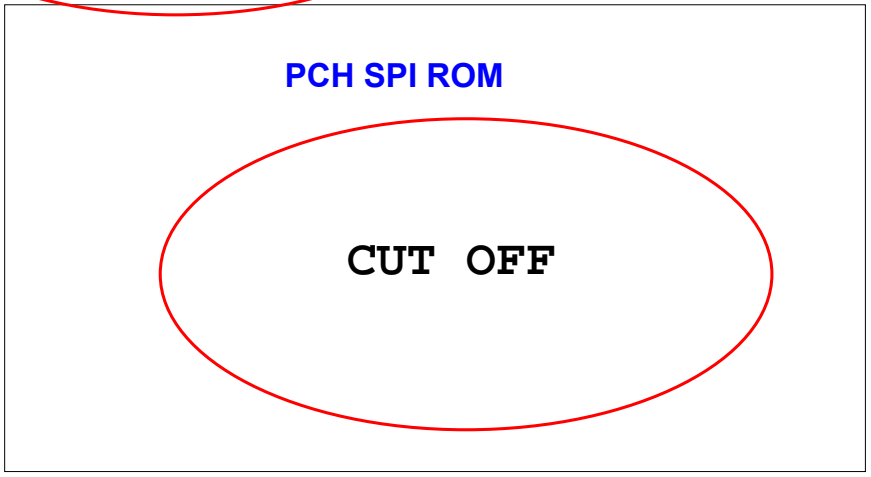
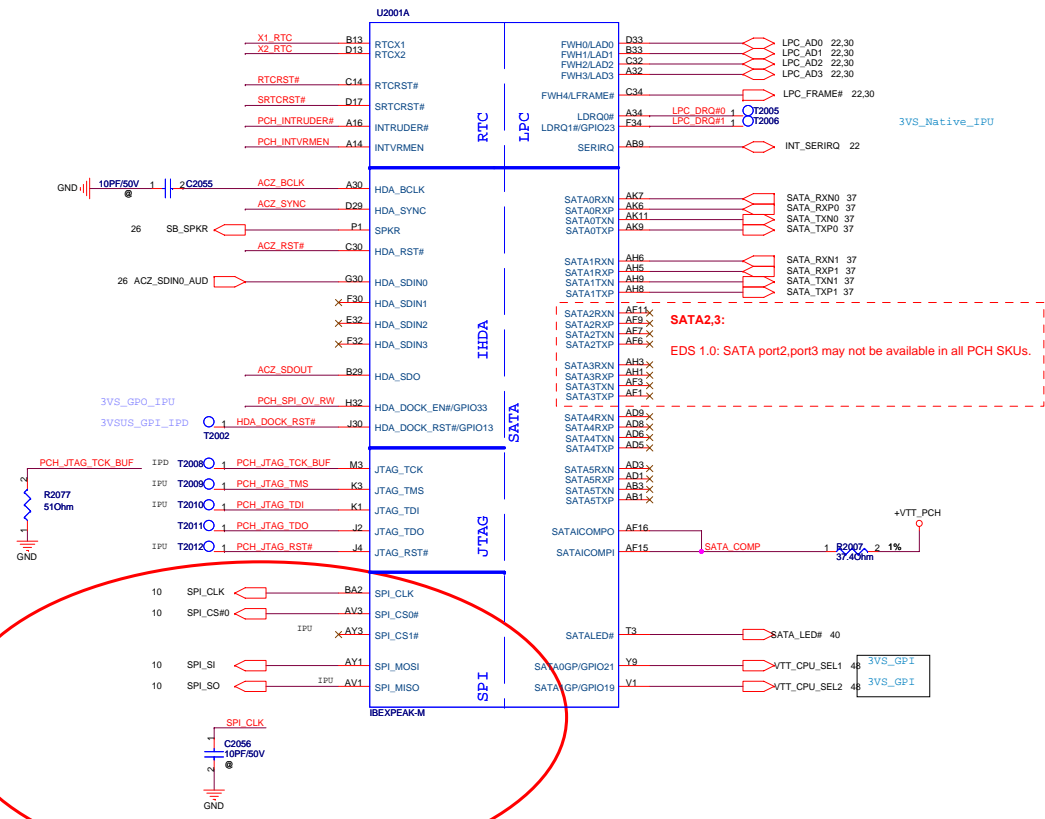
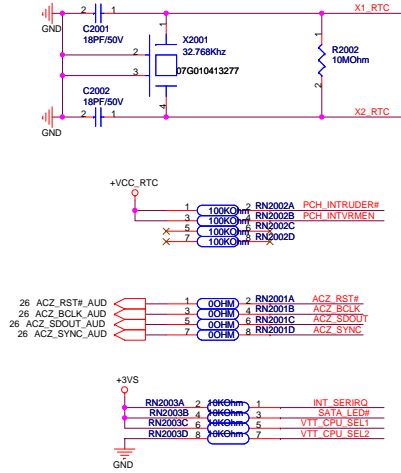
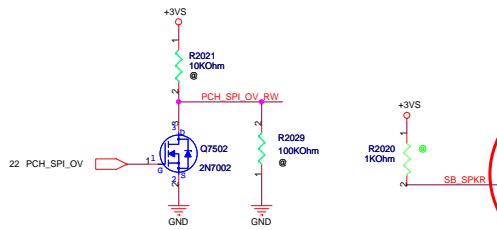
CMOS Settings		JRST2001		TPM Settings		JRST2002	
Clear CMOS	Shunt	Clear ME RTC Registers	Shunt	Clear ME RTC Registers	Shunt	Clear ME RTC Registers	Open (Default)
Keep CMOS	Open (Default)	Keep ME RTC Registers	Open (Default)	Keep ME RTC Registers	Open (Default)	Keep ME RTC Registers	Open (Default)

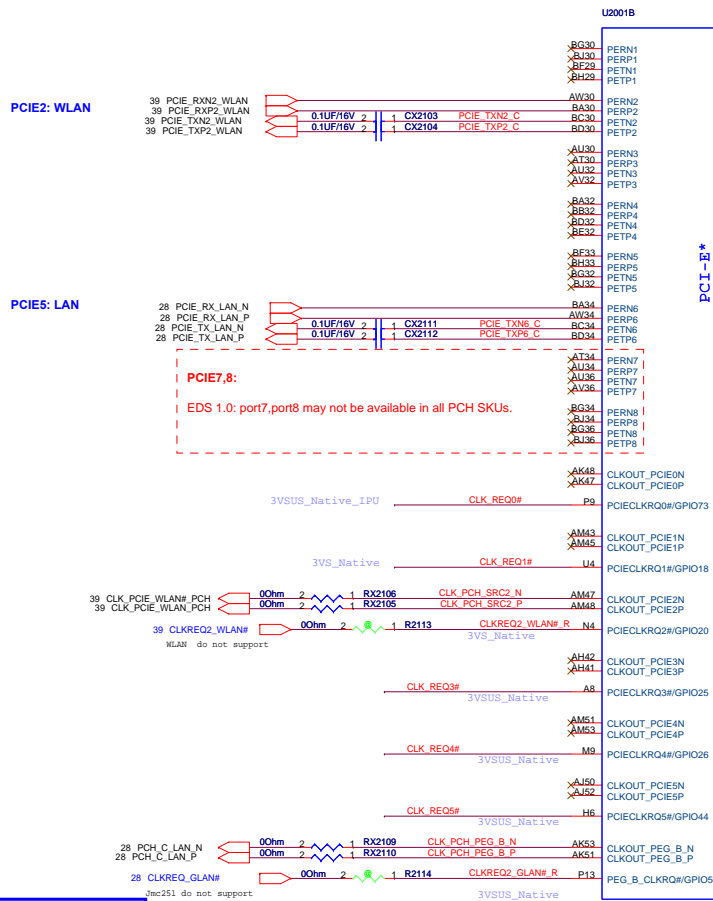


DG2.0 P297
 RTCRST# and SRPCRST# can not be shorted together

Strap information:

	B	L
ACZ_SYNC: Select VCCVSR 1.5V or 1.8V (IPD)	1.5V	1.8V
SB_SPKR: No reboot strap (IPD)	No reboot	Disable No reboot
PCH_SPI_OV_RW: (IPU)	No Flash ME FW	Flash ME FW
SPI_SI: ITPW strap. (IPB)	Enable	Disable
PCH_INTRVREM: Integrated 1.05 V VSM Enable /Disable	Enable	Disable

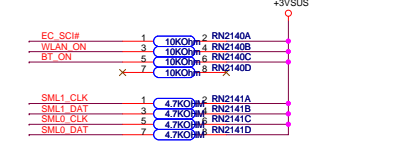
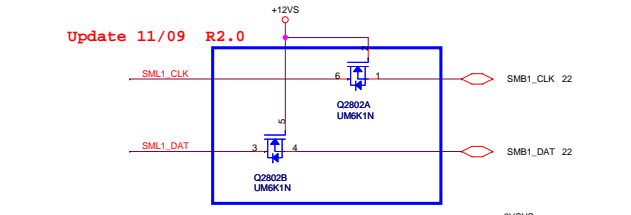
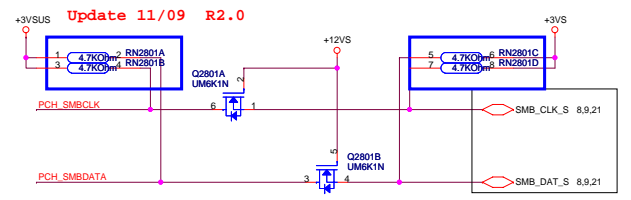
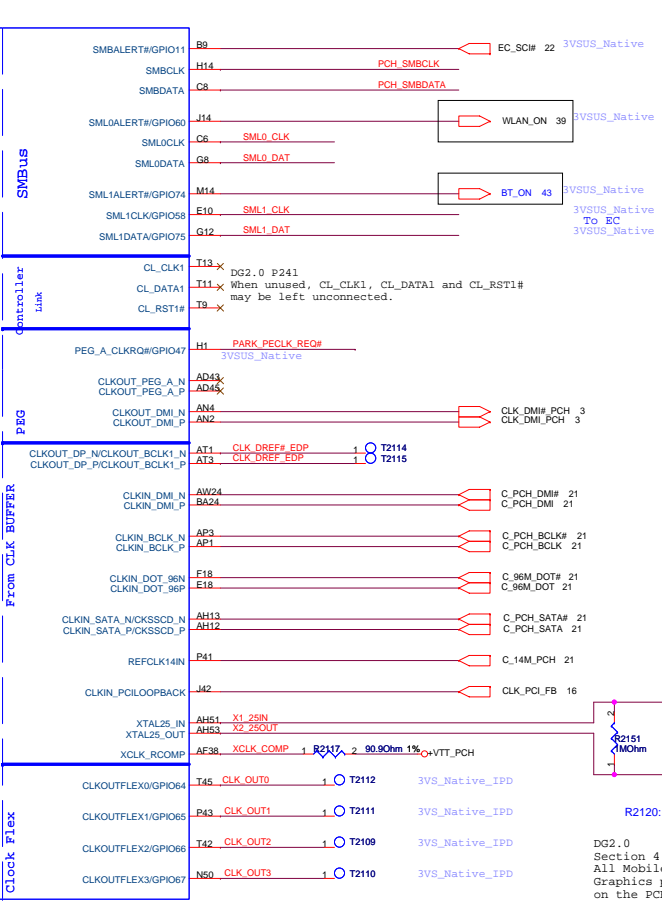
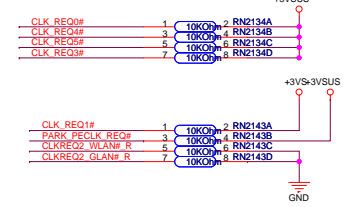




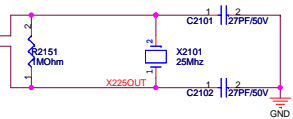
EDS 1.0: port7,port8 may not be available in all PCH SKUs.

Note: Place these resistors near to PCIe Slots

PCH CLKREQ Setting:
Not connected to device.



If not use crystal, please change C1201 to 0 Ohm



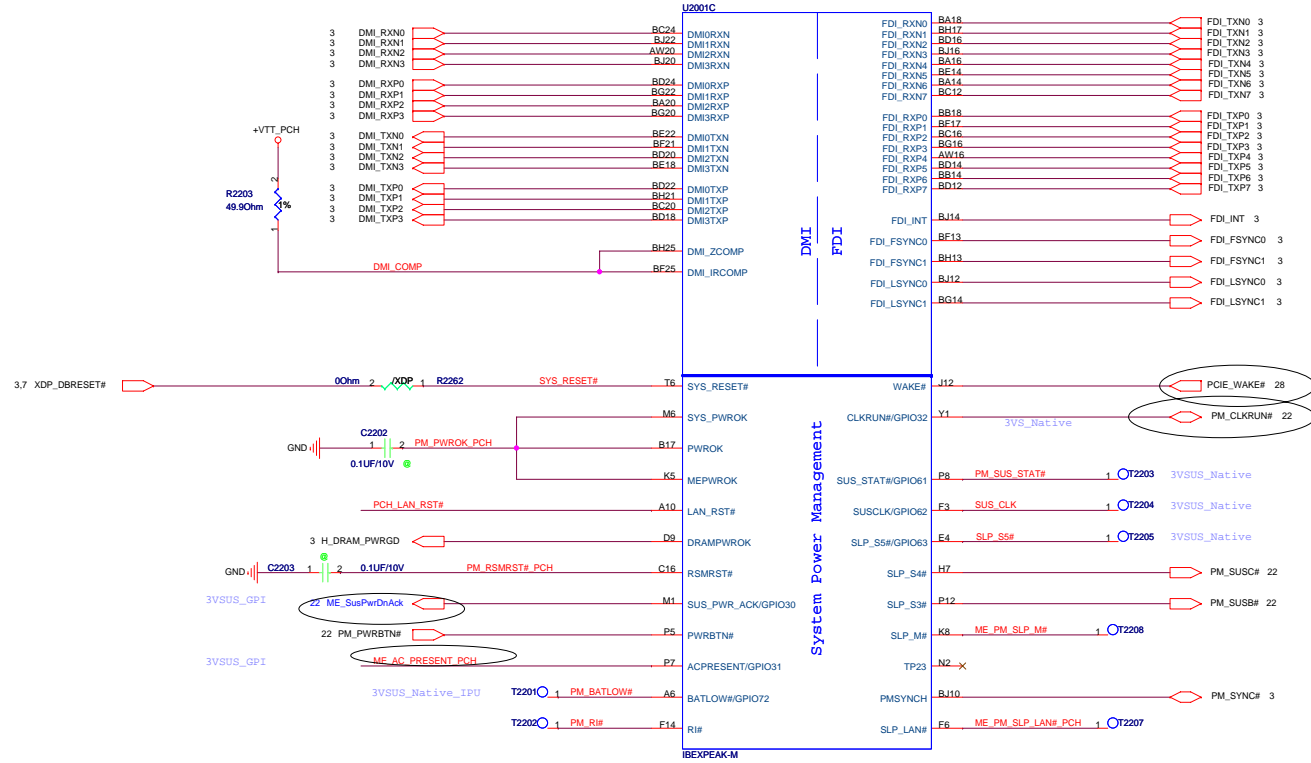
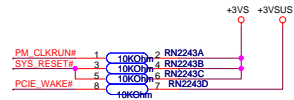
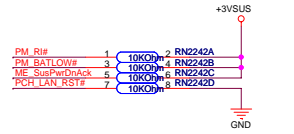
R2120: For Xtal measurement

DG2.0 Section 4.2.4.1: Added 25-MHz Crystal routing guideline. All Mobile Intel 5 Series Chipset-based Integrated Graphics platforms are required to use a 25-MHz crystal on the PCH XTAL25_IN/OUT to enable the PCH to generate the display clocks. Display Clock generation is integrated into the PCH.

Integrated Graphics platforms that implement DVI/DP/HDMI/e-DP are required to use Display Clock Integration (DCI) (25M crystal to generate PCH display clocks) to improve signal integrity and mitigate risk of electrical compliance and associated functional failures

WW35 Update: Integrated Graphics platforms that use only iVDS and/or VGA Displays may use Buffer Through Mode (BTM) and leave 25-MHz crystal and RC components unattached

pre-ES1 not support
Reversal Feature



R1.1,item L15

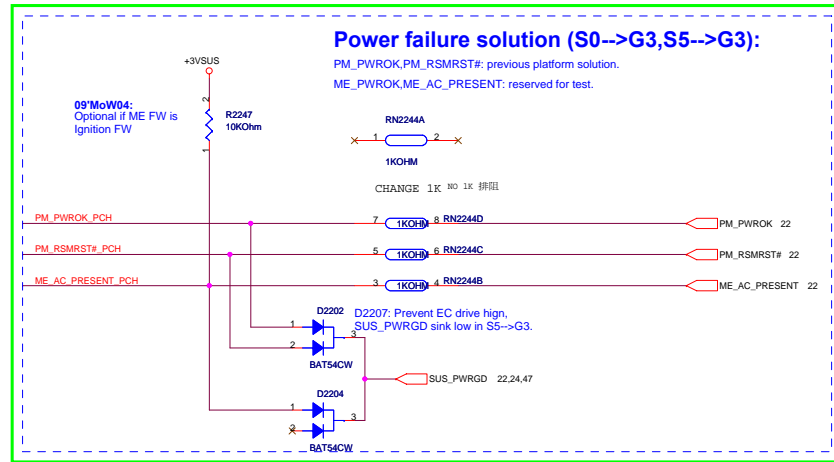
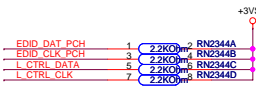


Table 112. Intel ME-EC Interaction Signal List with and without M3 Support

Signal Name	Platform with M3 Support (e.g., Intel® AHT)	Platform without M3 Support (e.g., Intel® ME Ignition Firmware)
SUS_PWR_DN_ACK (GPIO30)	Required	Required
ACPRESENT (GPIO31)	Required	Required Note: Optional if Intel ME FW is Intel® ME Ignition Firmware
SLP_M#	Required	Optional (Tie to SLP_S3#) Notes: If SLP_S3# is not routed from PCH to EC, then SLP_M# becomes required from Intel® ME-EC perspective.
SLP_S3#	Optional	Required Note: If SLP_M# is routed from PCH to EC, then SLP_S3# can be optional from Intel ME-EC perspective.

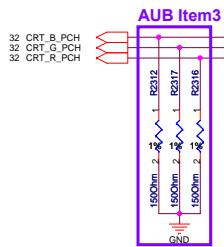
NOTE: Optional means that these signals are optional from Intel ME-EC interaction point of view. However, they are platform critical signals and are still required to be routed on the platform.

ME Ignition Firmware is for 2MB SPI core, only PM55 can support on it.



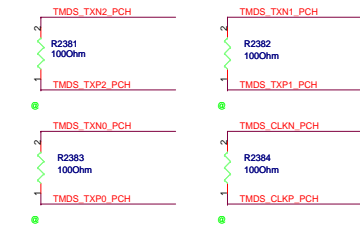
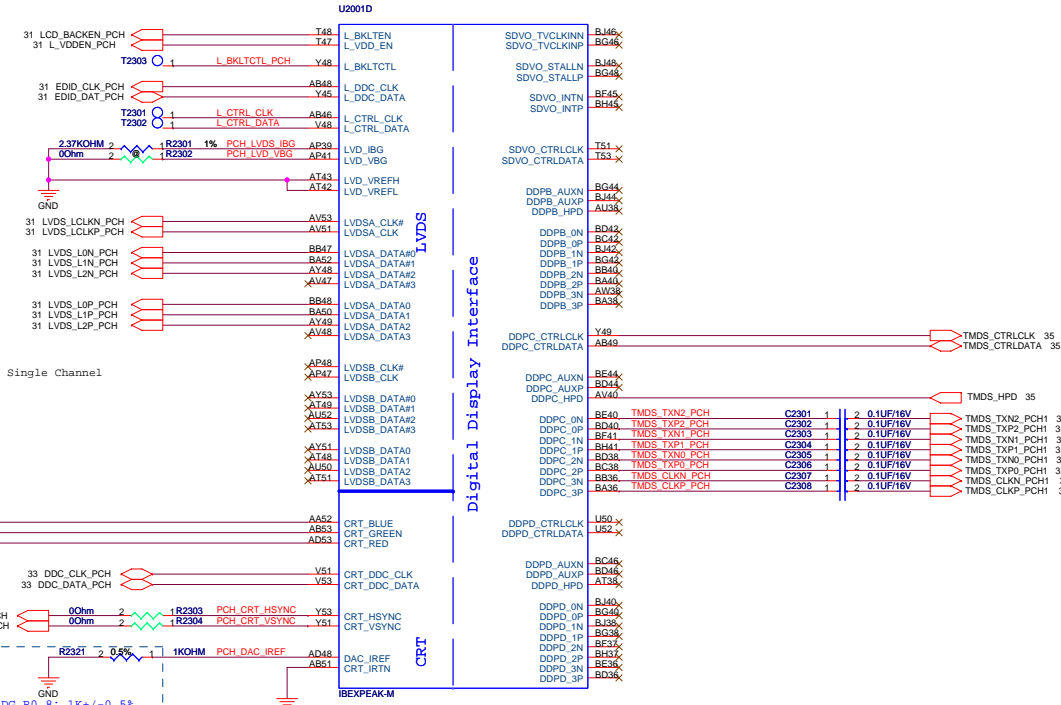
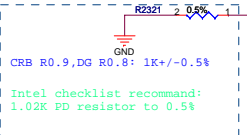
LVDS Disable: (For discrete graphic)

1. NC:
 LVDSA_DATA [3:0], LVDSA_DATA# [3:0],
 LVDSA_CLK, LVDSA_CLK#, LVDSB_DATA [3:0],
 LVDSB_DATA# [3:0], LVDSB_CLK, LVDSB_CLK#
 L_VDD_EN, L_BKLTEN, L_BKLTCTL, LVD_VREFH
 LVD_VREFL, LVD_IBG, LVD_VBG
2. Connected to GND:
 VccALVDS, VccTX_LVDS



CRT Disable: (For discrete graphic)

1. NC:
 CRT_RED, CRT_GREEN, CRT_BLUE
 CRT_HSYNC, CRT_VSYNC
2. 1-kΩ ±0.5% pull-down to GND:
 DAC_IREF
3. Connected to GND:
 CRT_ITRN
4. Connect to +V3.3:
 VCCDAC



U2001E

AD0 AD1 AD2 AD3 AD4 AD5 AD6 AD7 AD8 AD9 AD10 AD11 AD12 AD13 AD14 AD15 AD16 AD17 AD18 AD19 AD20 AD21 AD22 AD23 AD24 AD25 AD26 AD27 AD28 AD29 AD30 AD31 C/BE0# C/BE1# C/BE2# C/BE3#

NVRAM

PCI

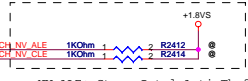
USB

PIRQA# PIRQB# PIRQC# PIRQD# REQ0# REQ1# REQ2# REQ3# GNT0# GNT1# GNT2# GNT3# INTA# INTB# INTC# INTD# INTF# INTG# INTJ# INTH# INTI# IRDY# PAR DEVSEL# FRAME# PLOCK# STOP# TRDY# PME# PLTRST# CLK_DSPPCI_R CLK_PCI_FB_R CLK_KBCPCI_PCH_R CLK_DEBUG_R CLK_DBGPCI2_R

NV_CE#0 NV_CE#1 NV_CE#2 NV_CE#3 NV_DQ#0 NV_DQ#1 NV_DQ#2 NV_DQ#3 NV_DQ#4 NV_DQ#5 NV_DQ#6 NV_DQ#7 NV_DQ#8 NV_DQ#9 NV_DQ#10 NV_DQ#11 NV_DQ#12 NV_DQ#13 NV_DQ#14 NV_DQ#15 NV_DQ#16 NV_DQ#17 NV_DQ#18 NV_DQ#19 NV_DQ#20 NV_DQ#21 NV_DQ#22 NV_DQ#23 NV_DQ#24 NV_DQ#25 NV_DQ#26 NV_DQ#27 NV_DQ#28 NV_DQ#29 NV_DQ#30 NV_DQ#31 NV_W#0 NV_W#1 NV_W#2 NV_W#3 NV_W#4 NV_W#5 NV_W#6 NV_W#7 NV_W#8 NV_W#9 NV_W#10 NV_W#11 NV_W#12 NV_W#13 NV_W#14 NV_W#15 NV_W#16 NV_W#17 NV_W#18 NV_W#19 NV_W#20 NV_W#21 NV_W#22 NV_W#23 NV_W#24 NV_W#25 NV_W#26 NV_W#27 NV_W#28 NV_W#29 NV_W#30 NV_W#31

Strap information:

Table with 3 columns: Strap Name, H, L. Rows include NV_ALE Strap Intel Anti-Theft Technology HDD Data Protection Enable and NV_CLE Strap DMI Termination Voltage.



NV_ALE: Strap Intel Anti-Theft Technology HDD Data Protection Enable. (H: enable) NV_CLE: Strap DMI Termination Voltage

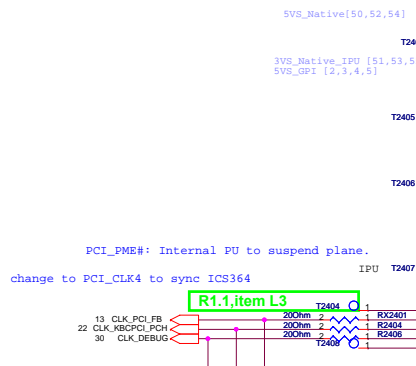
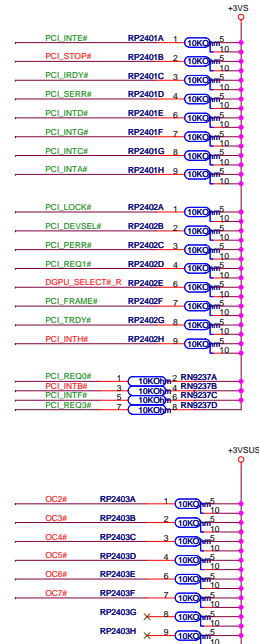
Table with 3 columns: K82JR, Recommend settings. Rows include USB port, WiFi/WiMax, Camera, and BT (1.1).

USBPN# USBP# J18 J19 A18 C18 N20 P20 USBP# J20 J21 J22 J23 J24 J25 J26 J27 J28 J29 J30 J31 J32 J33 J34 J35 J36 J37 J38 J39 J40 J41 J42 J43 J44 J45 J46 J47 J48 J49 J50 J51 J52 J53 J54 J55 J56 J57 J58 J59 J60 J61 J62 J63 J64 J65 J66 J67 J68 J69 J70 J71 J72 J73 J74 J75 J76 J77 J78 J79 J80 J81 J82 J83 J84 J85 J86 J87 J88 J89 J90 J91 J92 J93 J94 J95 J96 J97 J98 J99 J100



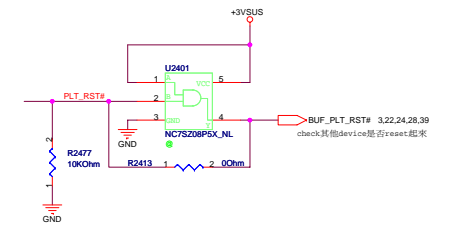
OC0#/GPIO59 OC1#/GPIO40 OC2#/GPIO41 OC3#/GPIO42 OC4#/GPIO43 OC5#/GPIO9 OC6#/GPIO10 OC7#/GPIO14

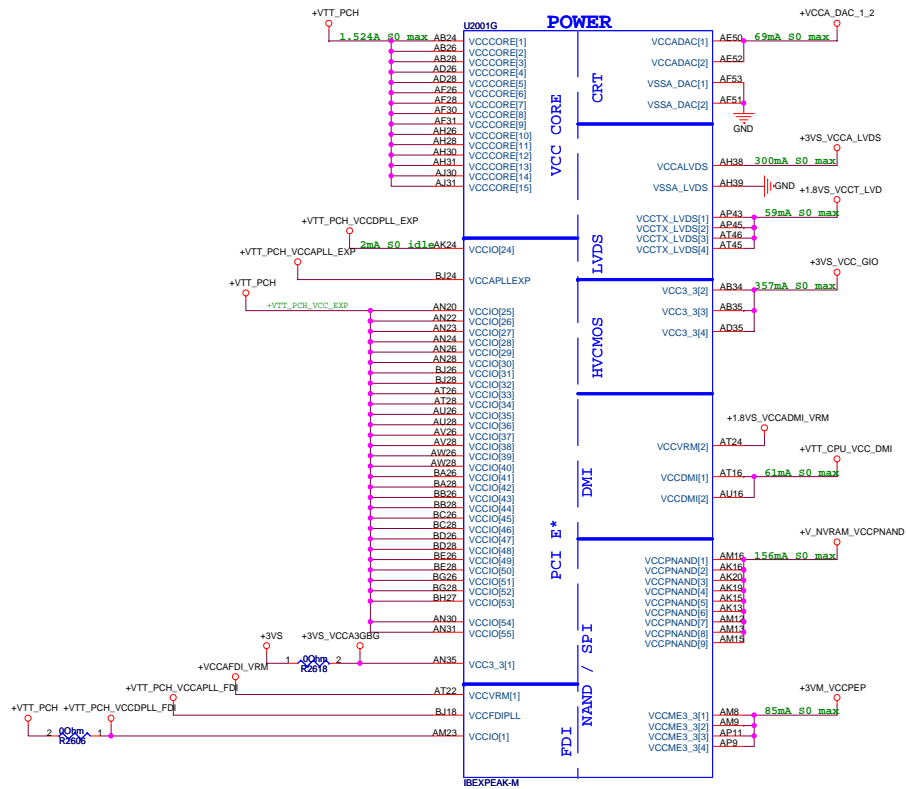
3VSUS_Native [9,10,14,40,41,42,43,59]



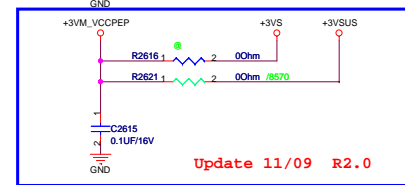
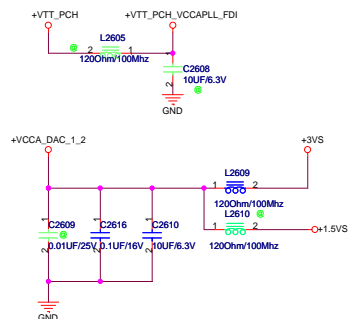
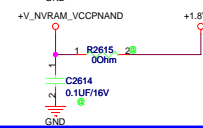
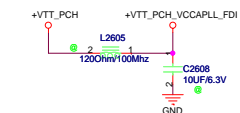
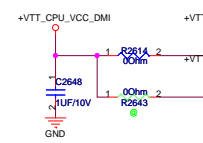
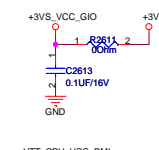
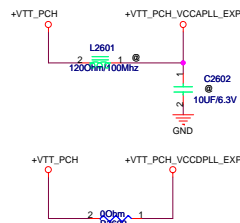
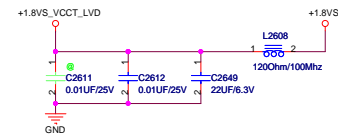
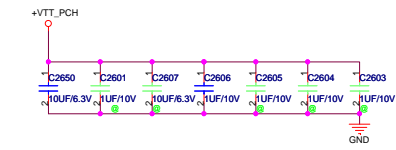
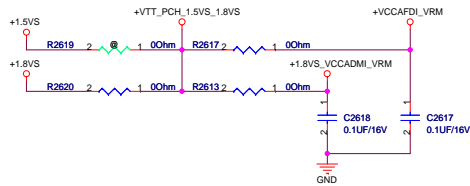
GNT0#,GNT1#: Boot BIOS Strap. Table with 3 columns: PCL_GNT#0, PCL_GNT#1, Boot BIOS Location. Includes circuit diagram for PCL_GNT#0 and PCL_GNT#1.

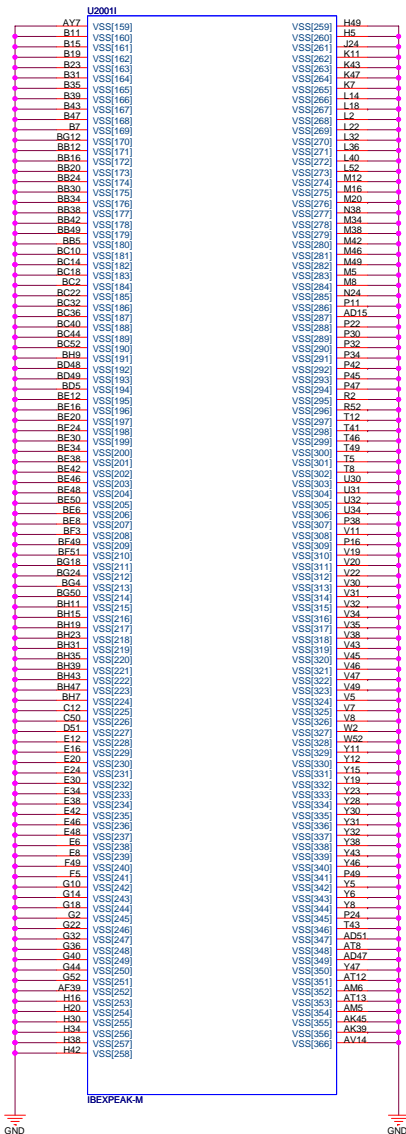
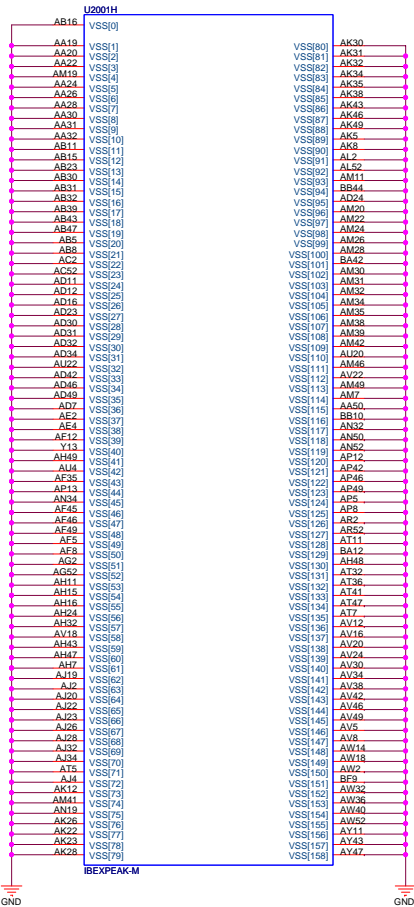
GNT3#: A16 swap override Strap/ Top-Block swap override jumper. Table with 2 columns: Low=Enabled A16 swap override/ Top-Block swap override, High=Default. Includes circuit diagram for PCL_GNT3#.

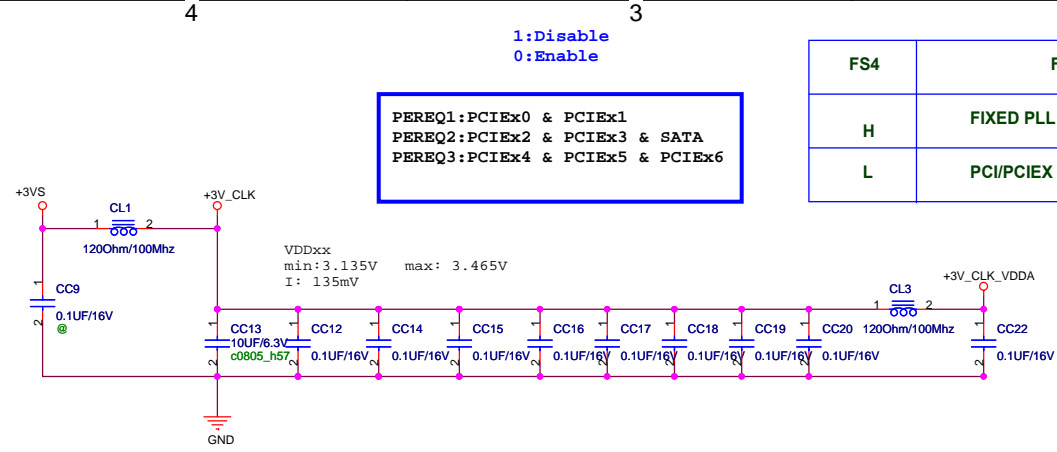
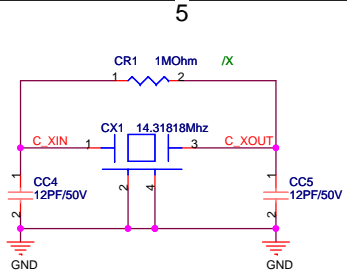




HDA_SYNC: Select VCCVRM 1.5V or 1.8V (IPD)
 Low: 1.8V
 High: 1.5V

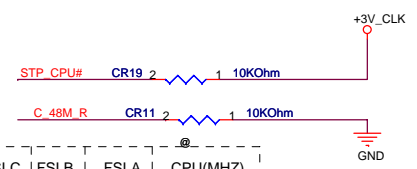
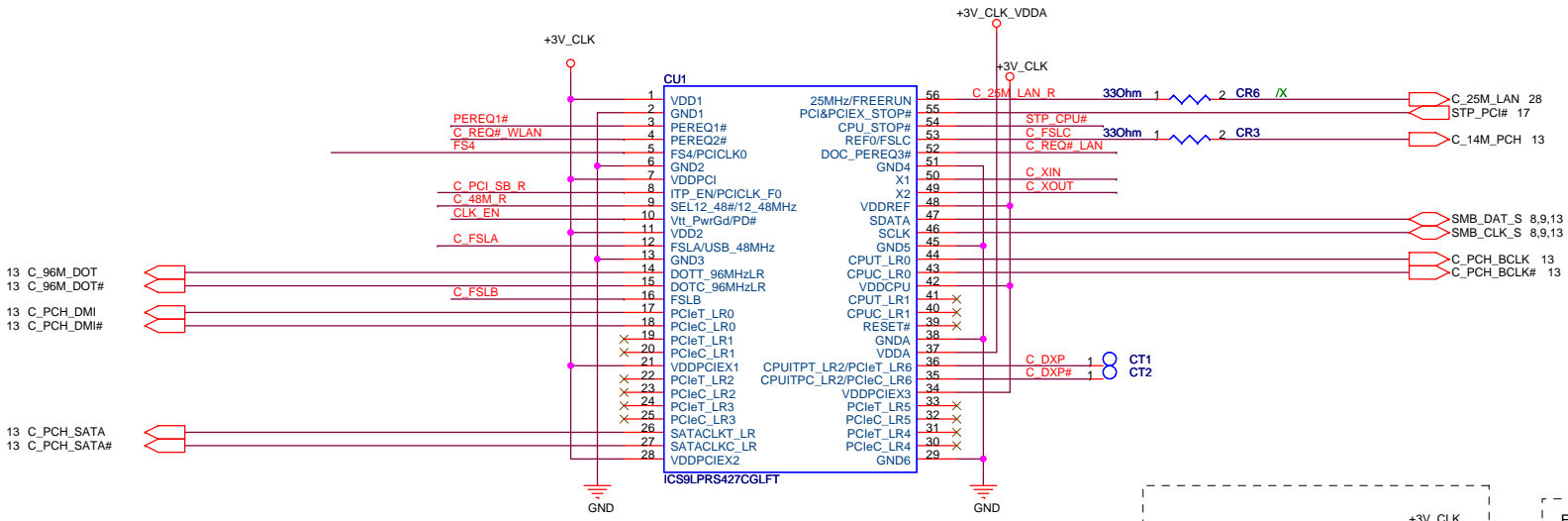




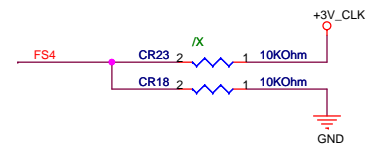
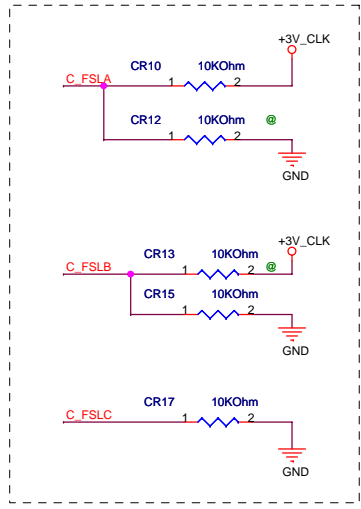
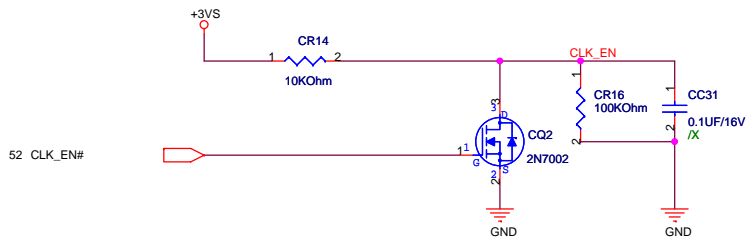
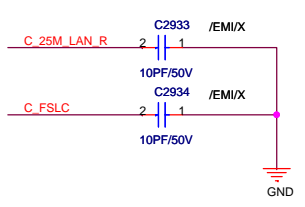
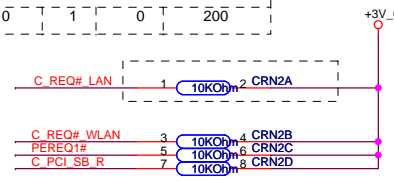


PEREQ1:PCIEx0 & PCIEx1
 PEREQ2:PCIEx2 & PCIEx3 & SATA
 PEREQ3:PCIEx4 & PCIEx5 & PCIEx6

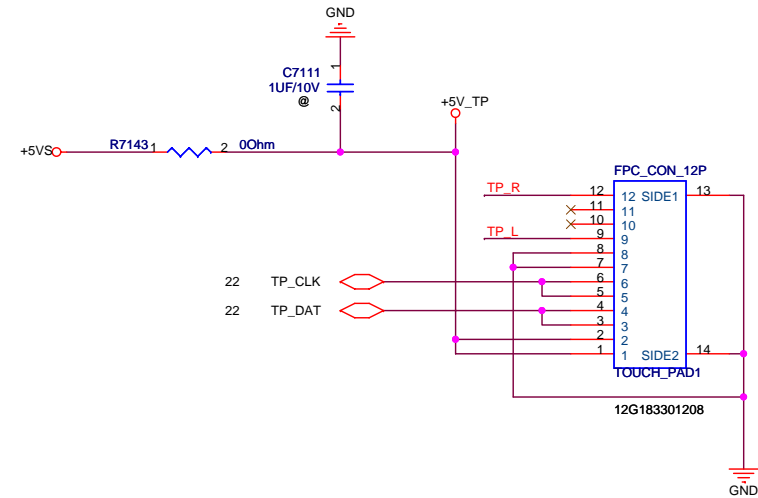
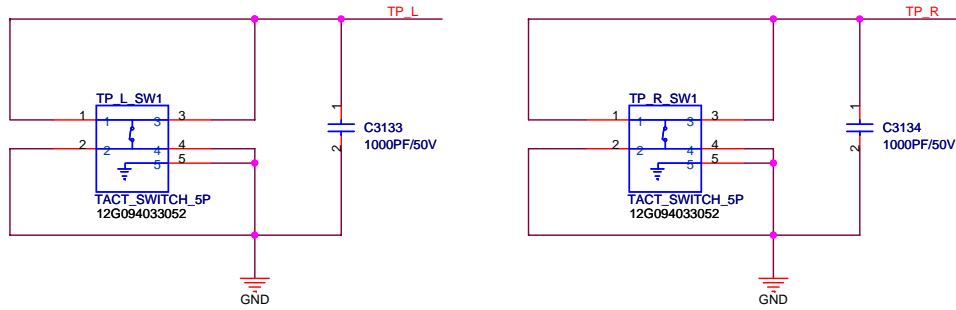
FS4	Function
H	FIXED PLL (Asynchronous)
L	PCI/PCIEX PLL(synchronize)



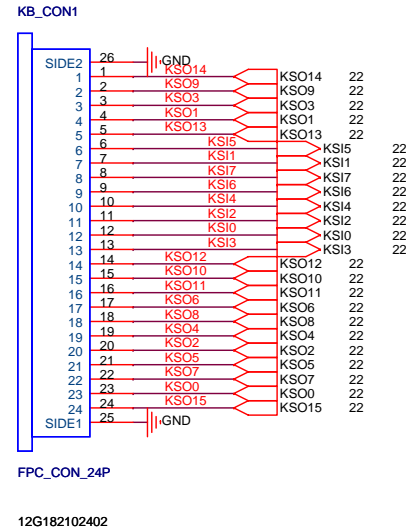
FSLC	FSLB	FSLA	CPU(MHZ)
0	1	1	166
0	0	1	133
0	1	0	200



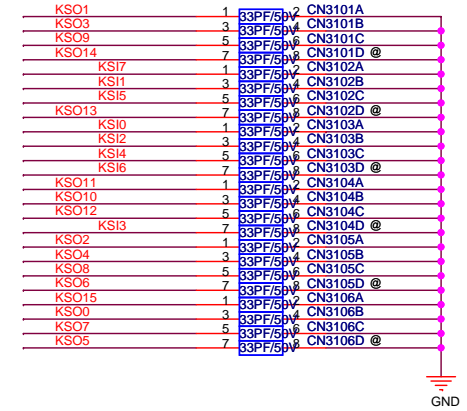
TouchPad



Keyboard Connector



EMI Request



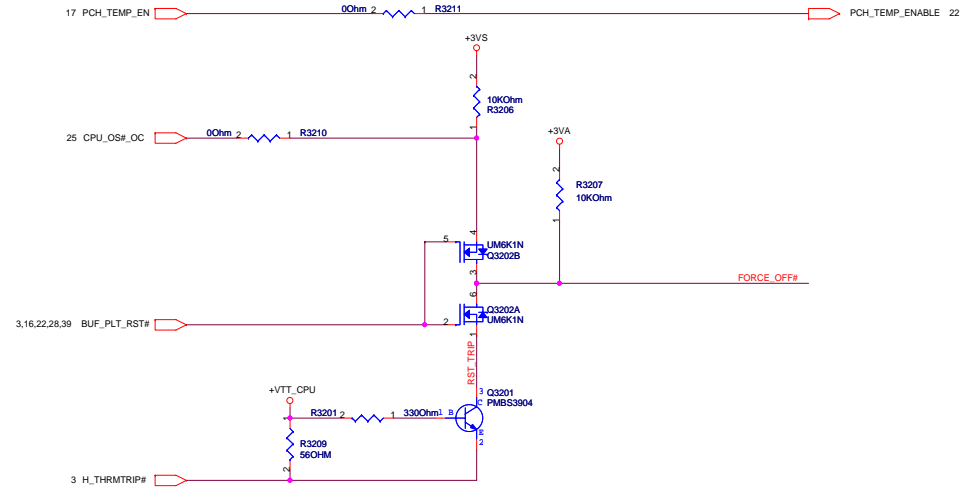
<Variant Names>

Thermal Policy

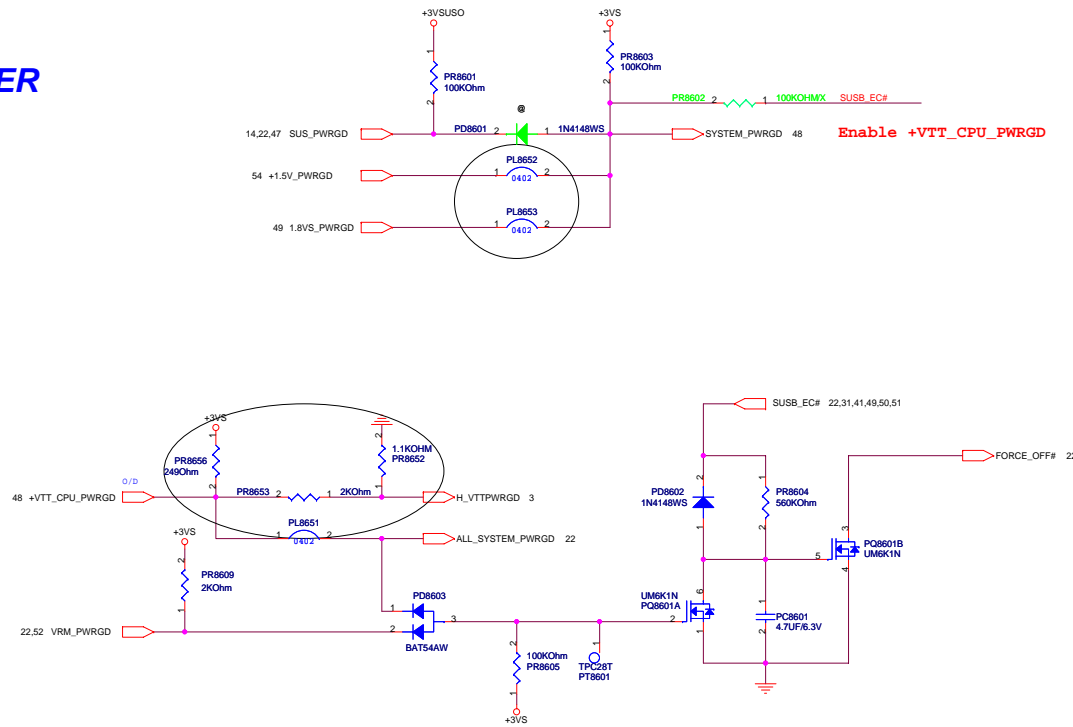
Input 1(sensor)

Input 2(thermtrip)

Output (shut down)

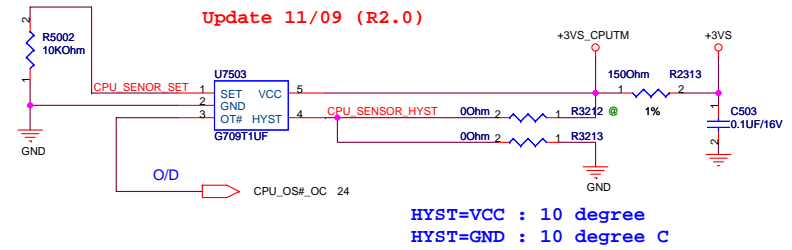


POWER GOOD DETECTOR



GPU Thermal Sensor

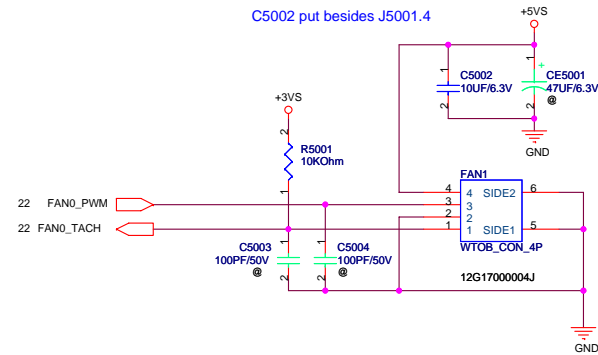
CPU Thermal Sensor



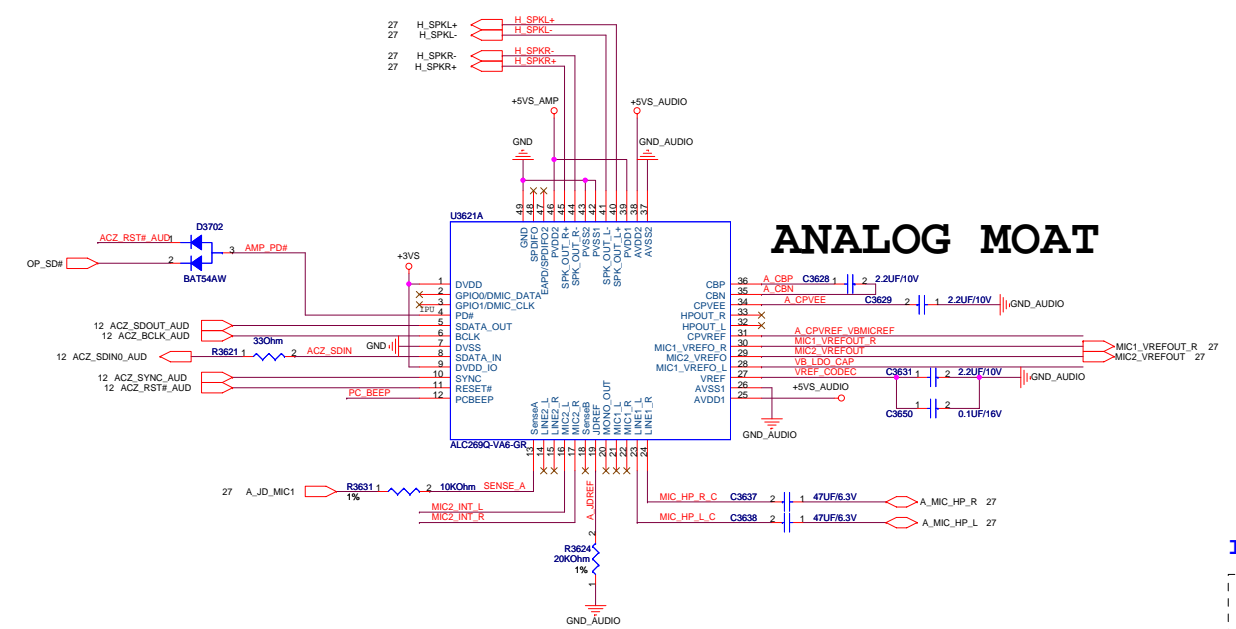
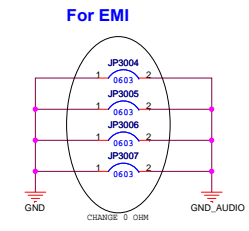
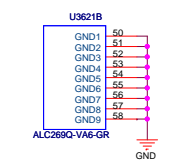
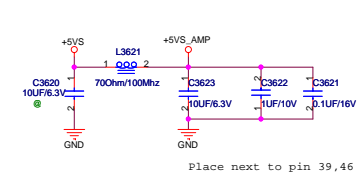
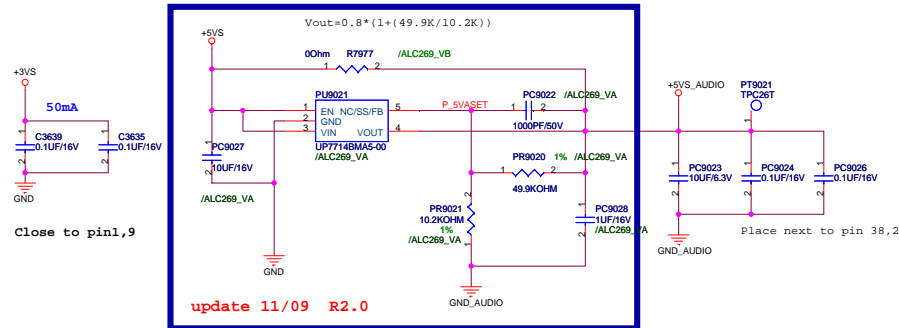
U7503 under CPU socket

PWM Fan

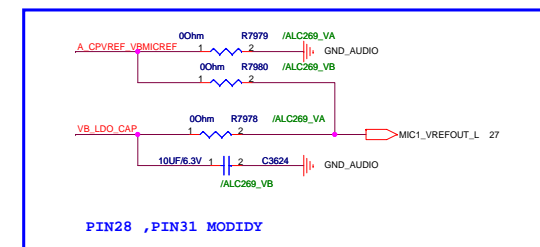
Remove diode(+5Vs to GND)
for using 4-wires PWM FAN.



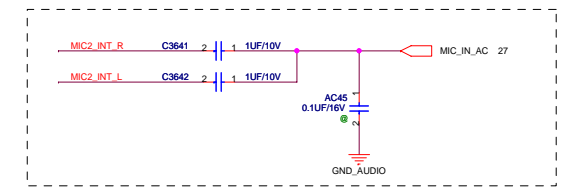
ASUS		Title : AR8131	
ASUSTeK COMPUTER INC		Engineer:	
Size	Project Name		Rev
Custom	K42F		1.0
Date: Thursday, November 12, 2009		Sheet	25 of 59



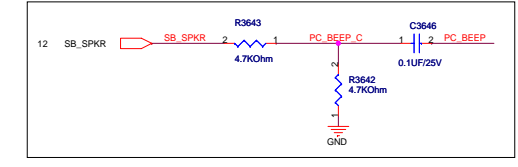
update 11/09 R2.0



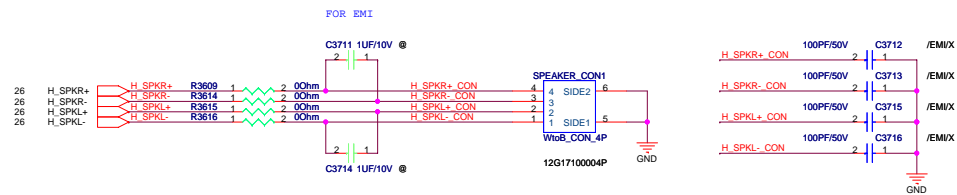
INTERNAL MIC



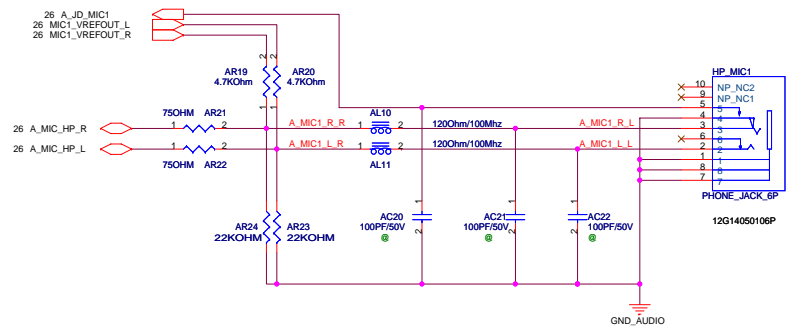
PC BEEP



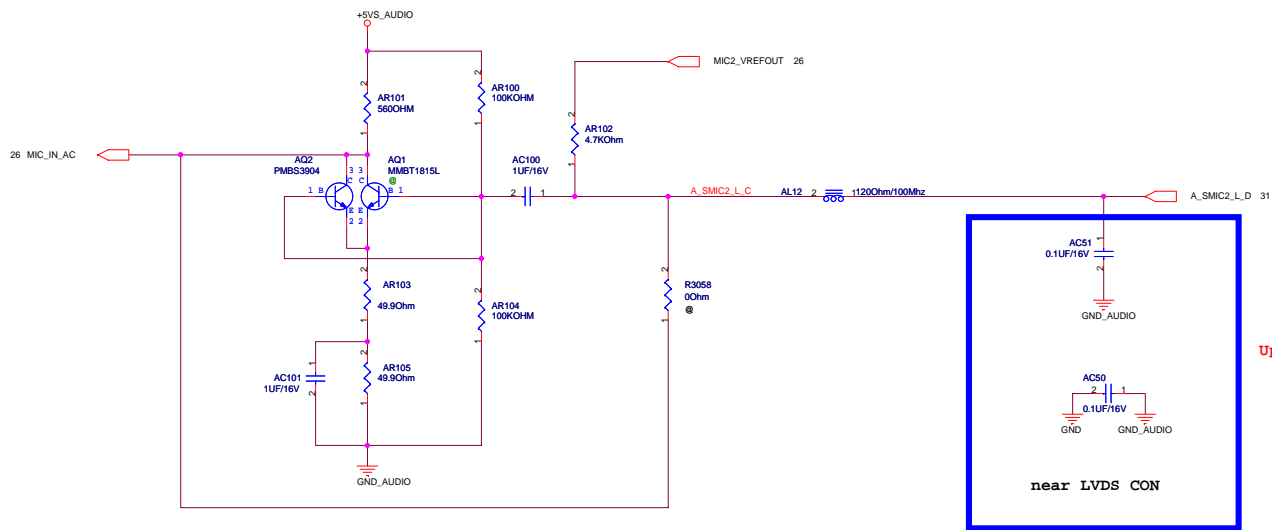
SPEAKER



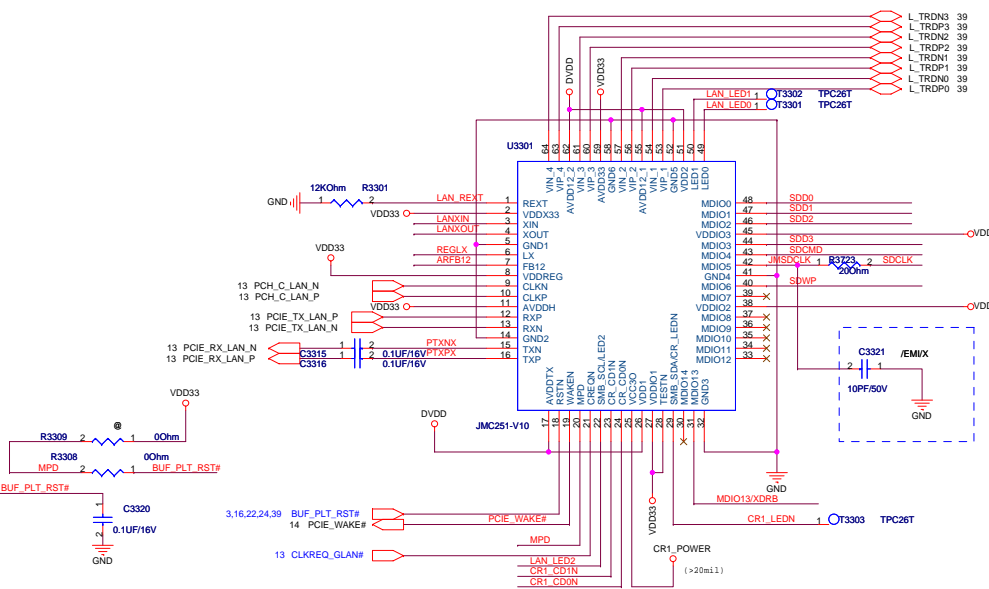
HP and MIC



Internal MIC and AMP

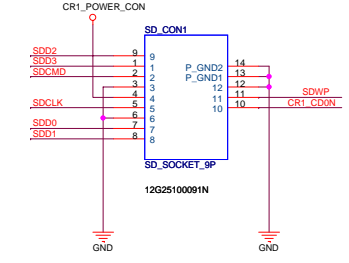


Update 11/09 R2.0

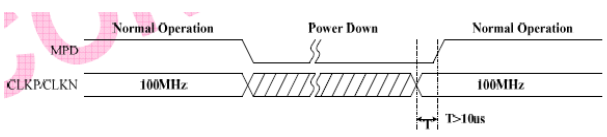
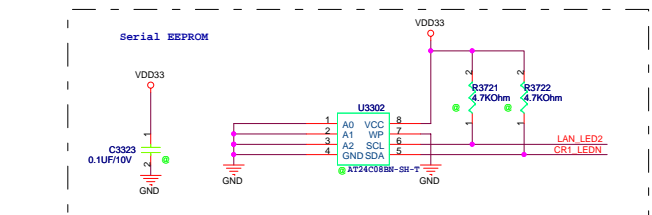
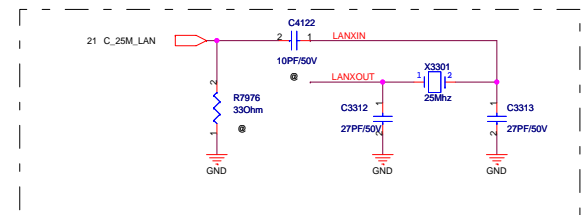
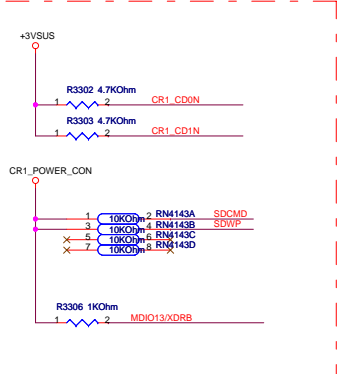
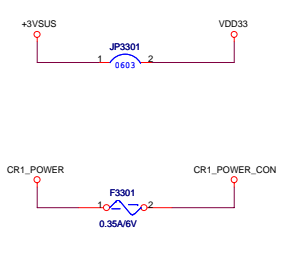
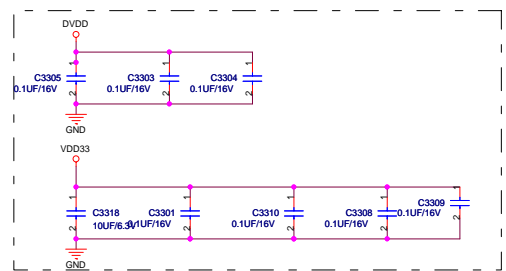
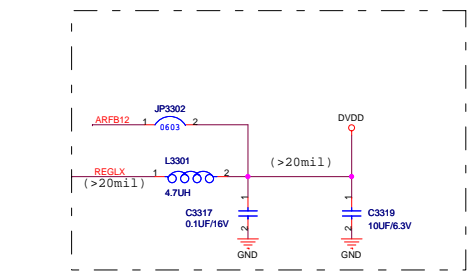


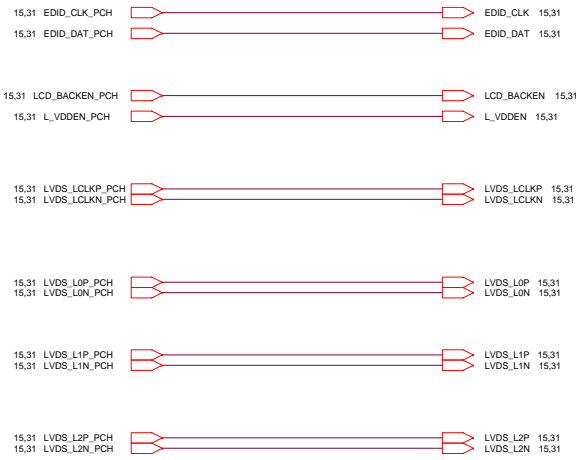
SDWP: Internal Pull-down (DIOL)
SDCDN: Internal Pull-up (DIH)

SDWP = 1 Write protect
SDWP = 0 Write-able
SDCDN = 1 No card
SDCDN = 0 Card inserted

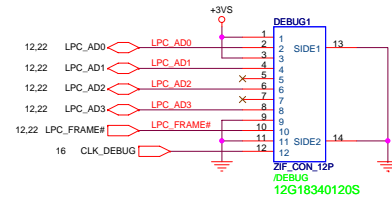


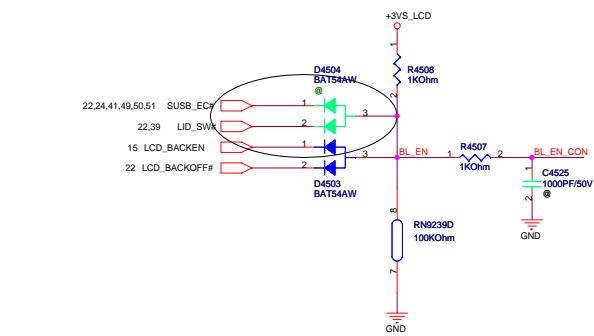
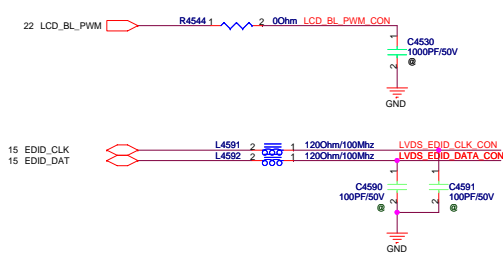
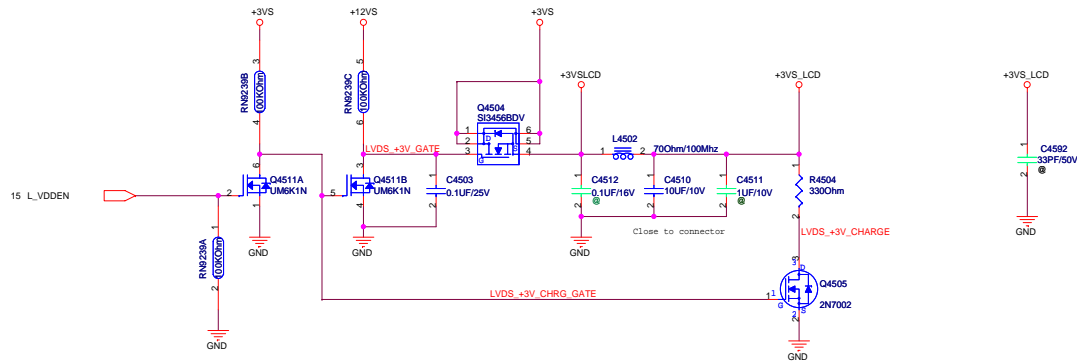
Card Insert: Pin.10 and Pin.12 are Shorted.
Card not Insert: Pin.10 and Pin.12 are Opened.
Write Protect: Pin.11 and Pin.12 are Opened.
Write Enable: Pin.11 and Pin.12 are Shorted.



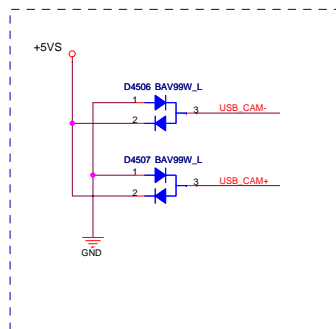
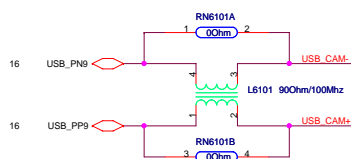


LPC Debug Port

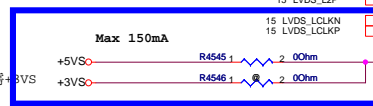




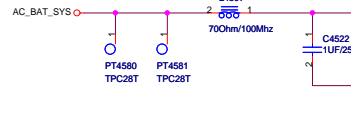
Camera USB



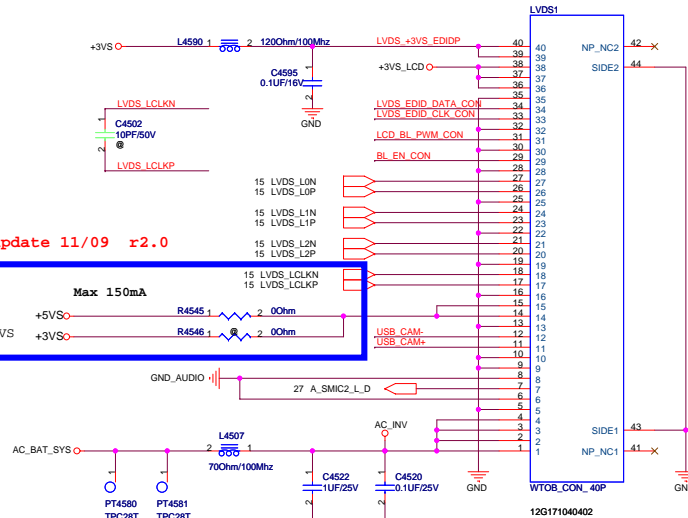
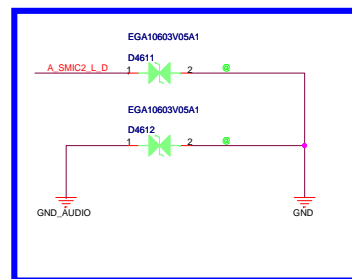
update 11/09 r2.0

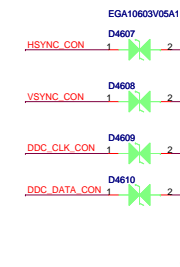
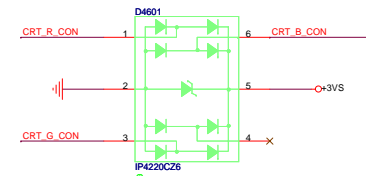
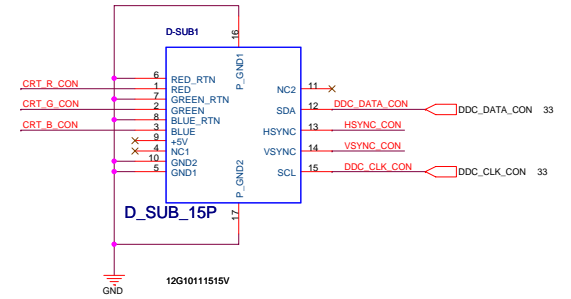
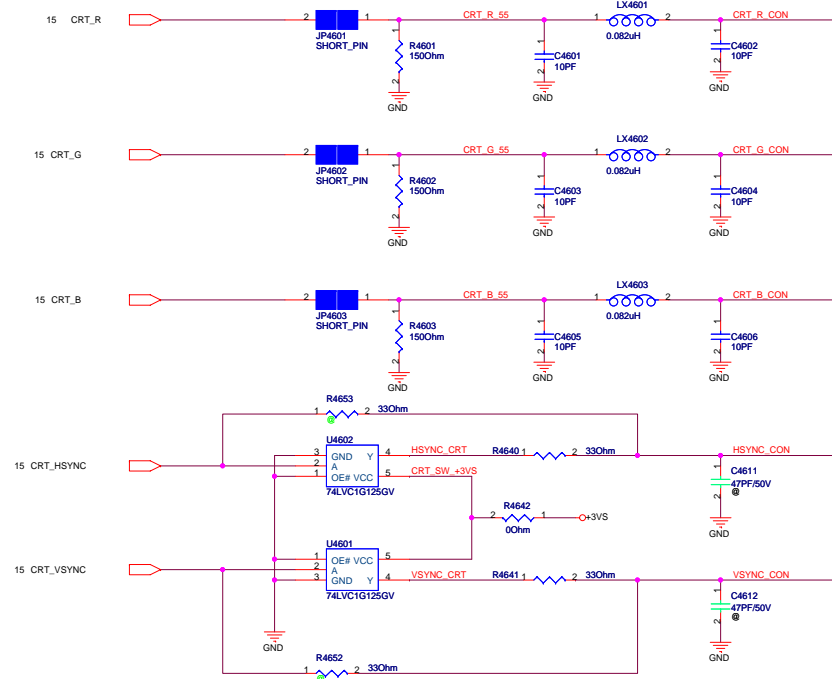


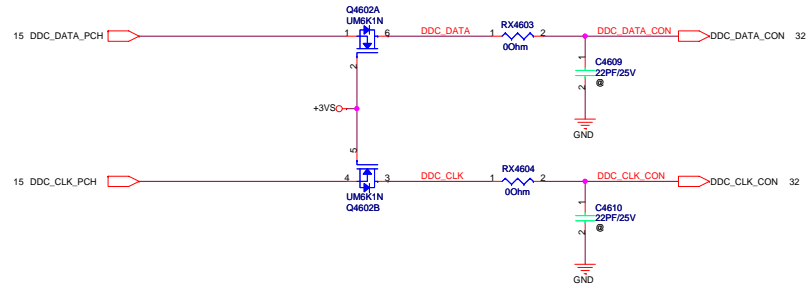
CNP9059 Camera 導入時

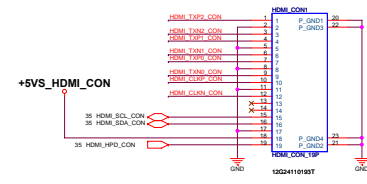
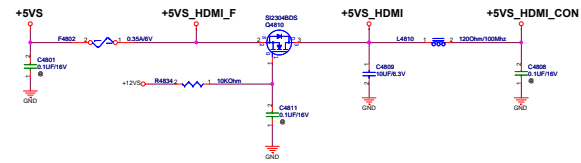
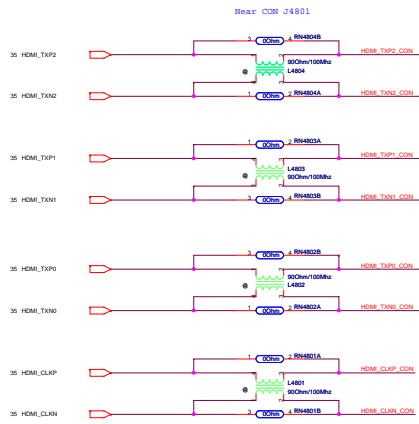


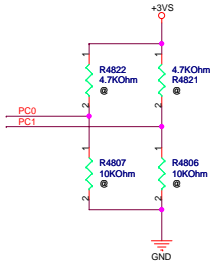
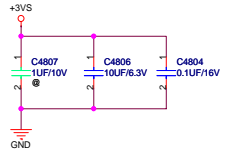
update 11/09 r2.0



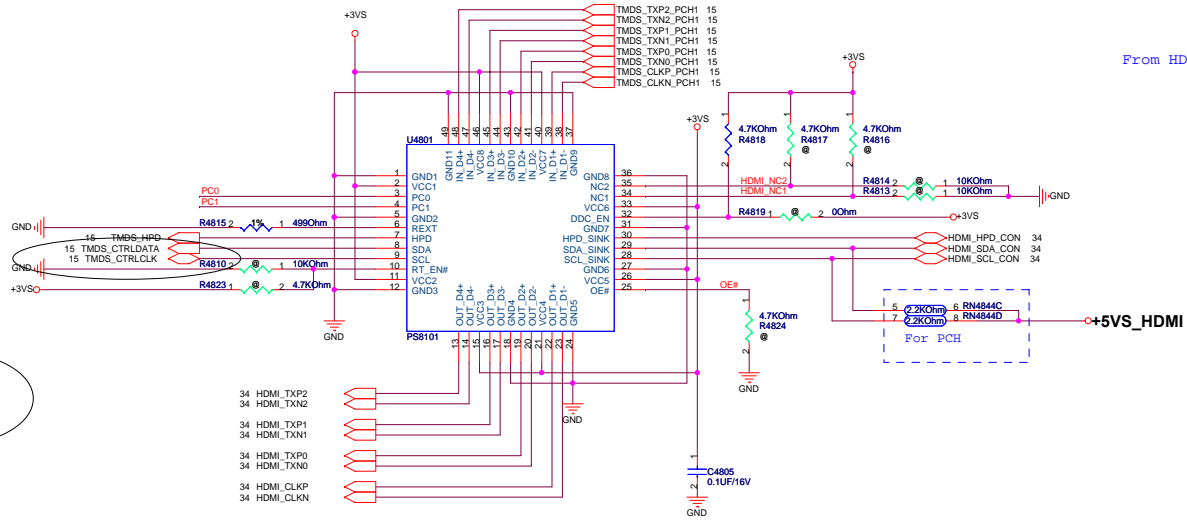




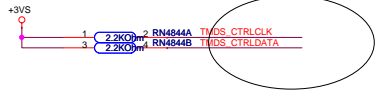




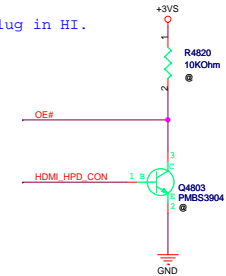
Change to PS8101



If using Parade PS8101 Level Shifter, pin 4 pin 3
Recommended Equalization[PC1,PC0]=00,8dB

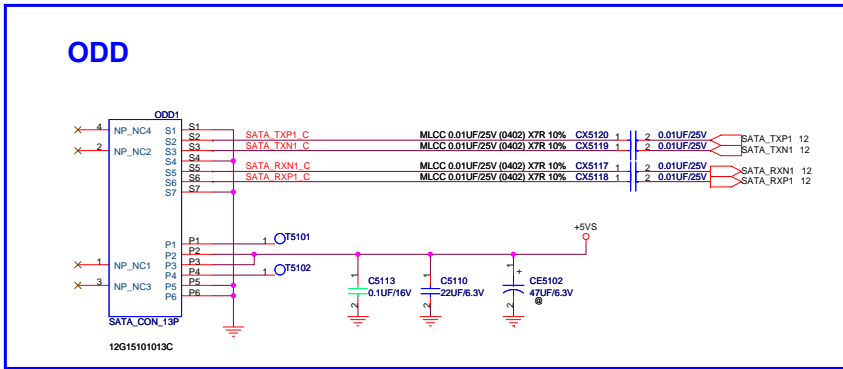


From HDMI Con. Plug in HI.

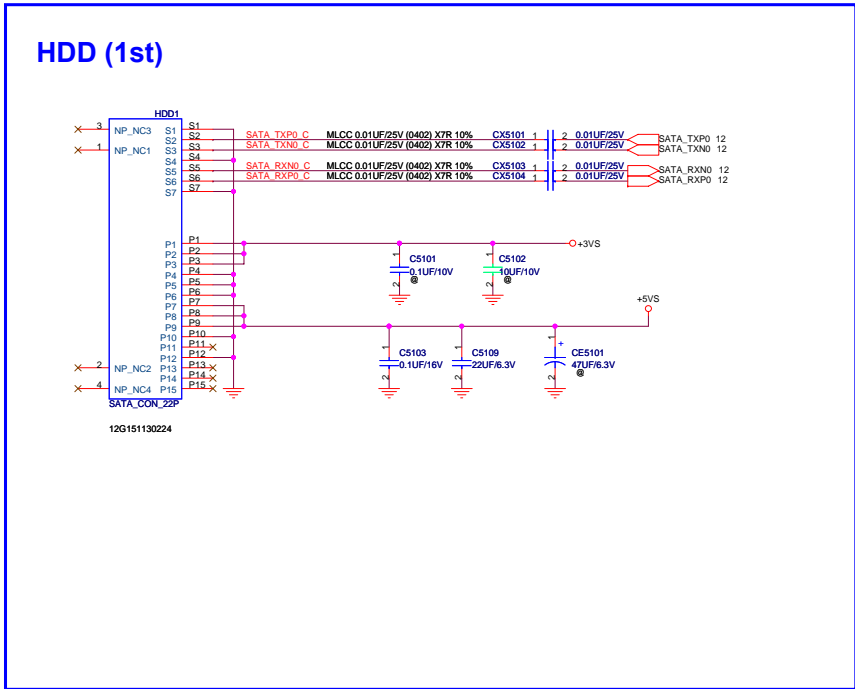




ODD

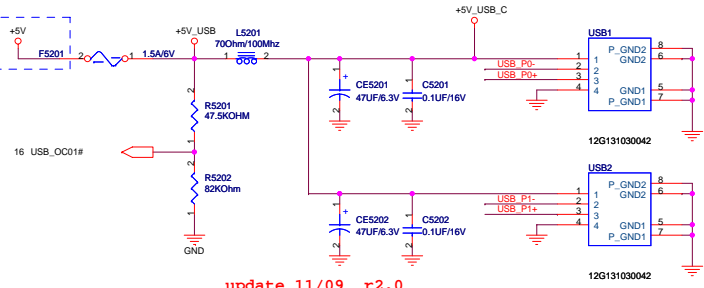


HDD (1st)

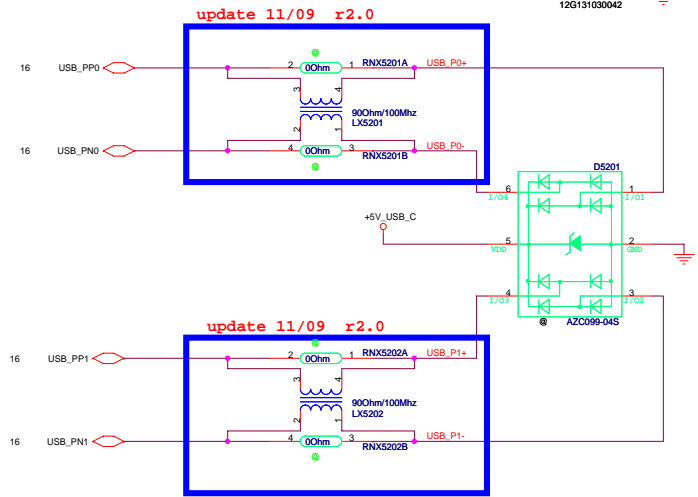


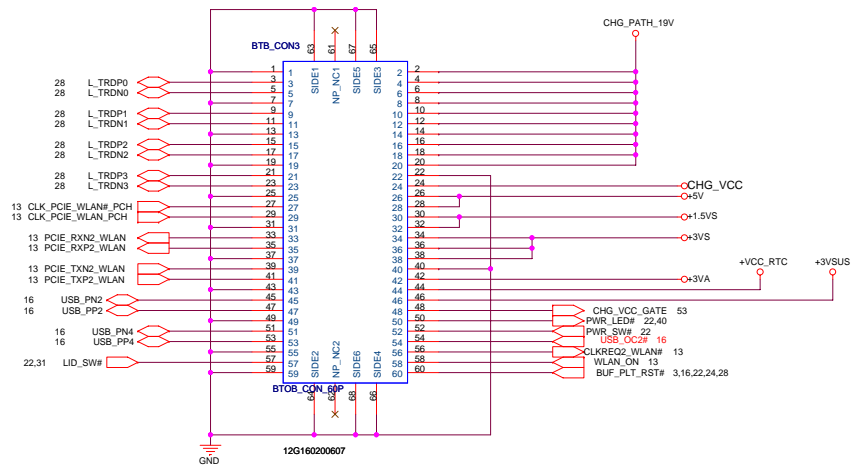
USB ports

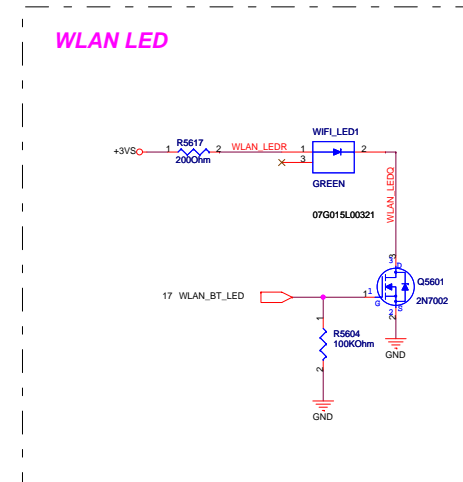
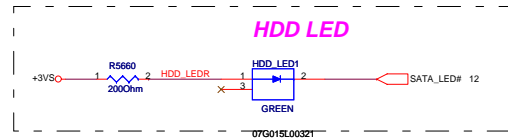
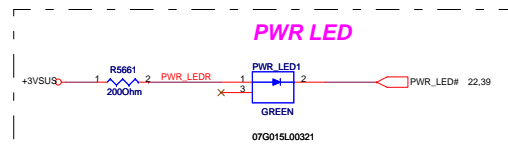
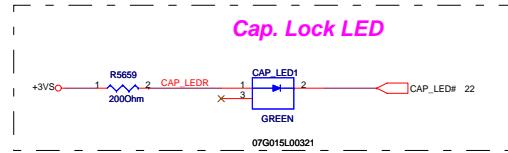
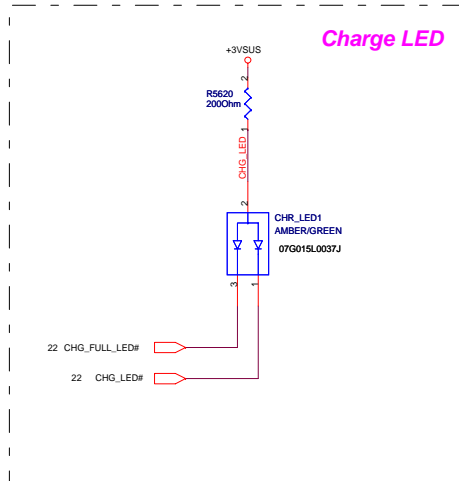
Combine power because these two ports are nearby.



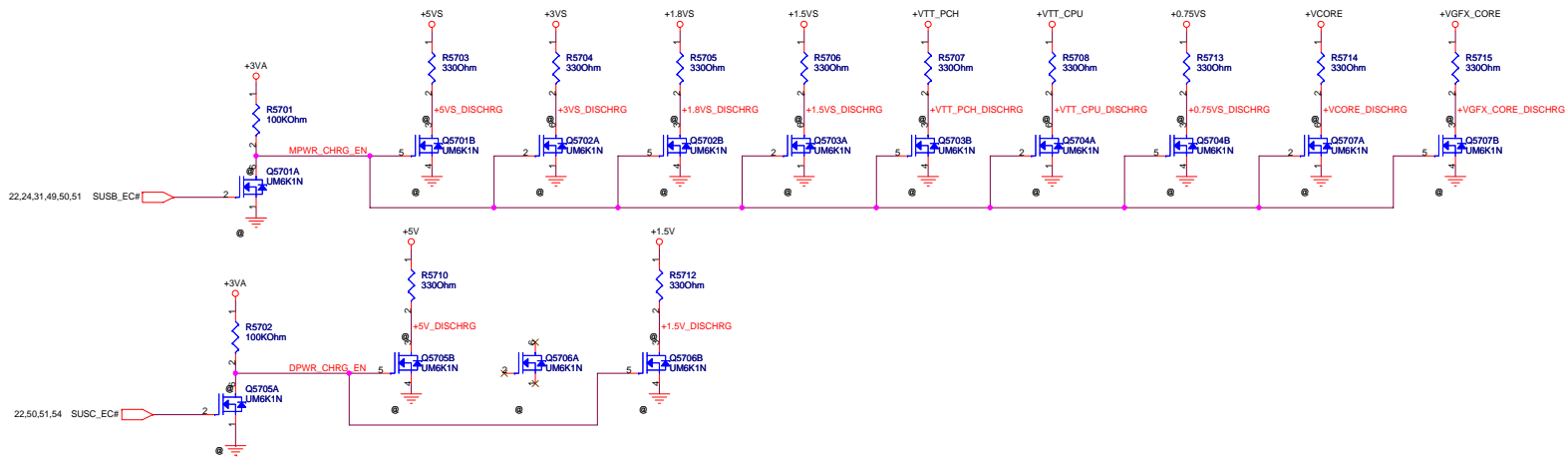
Change USB PIN1234 to 4321

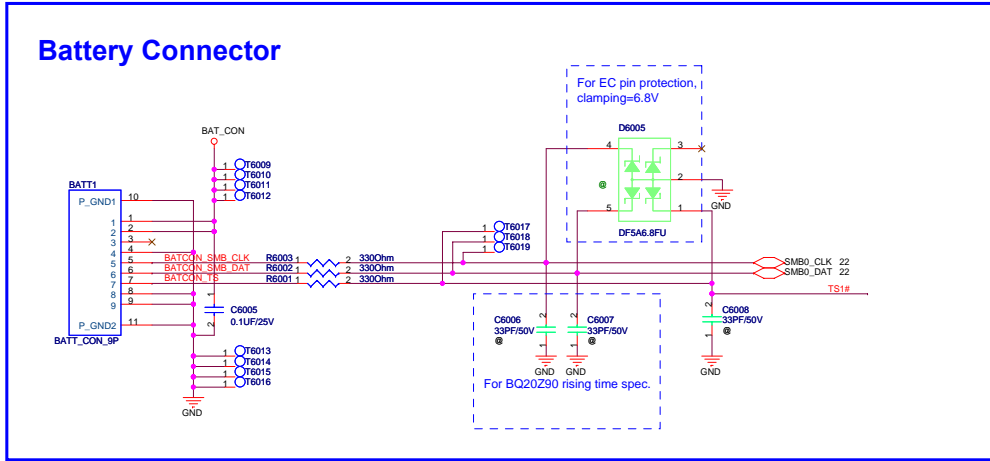




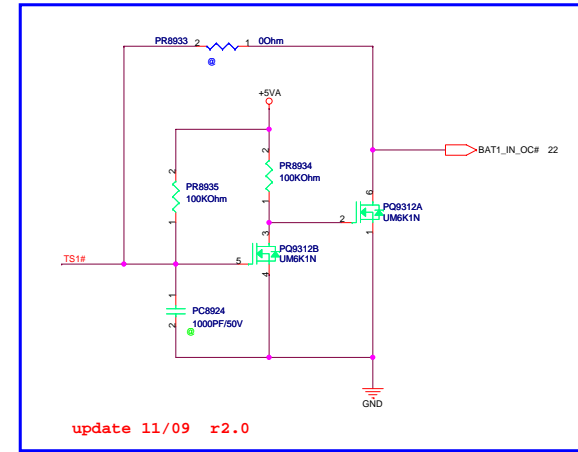


Remove +2.5Vs is for ATI GFX

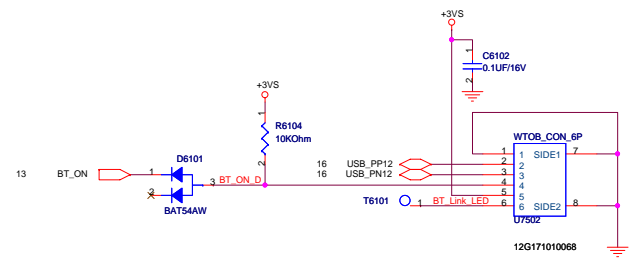




Battery IN DETECT

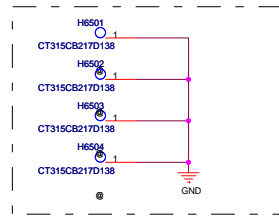


BLUETOOTH

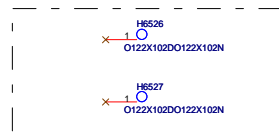


Main Board

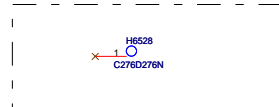
For CPU

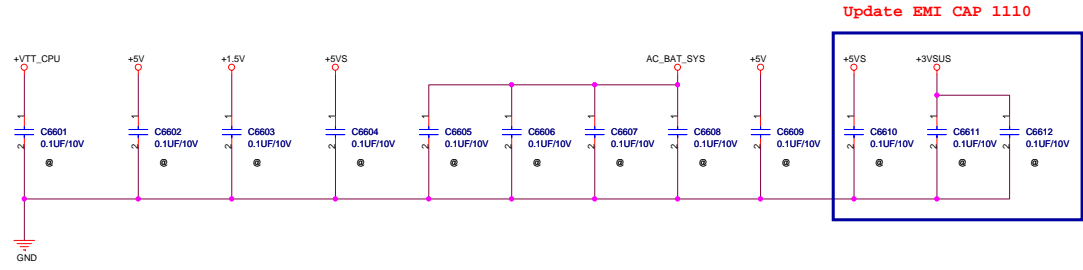


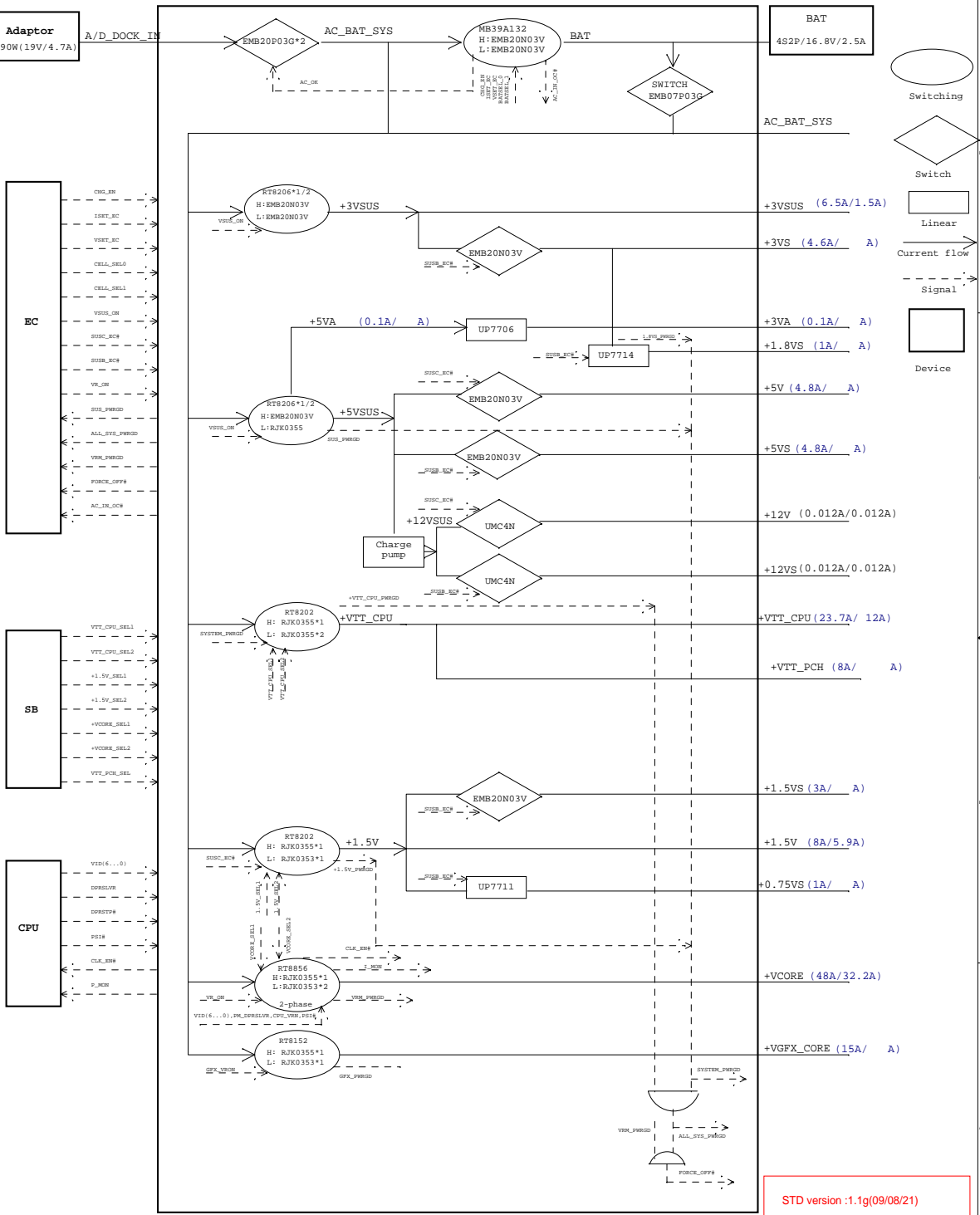
For 橢圓定位孔



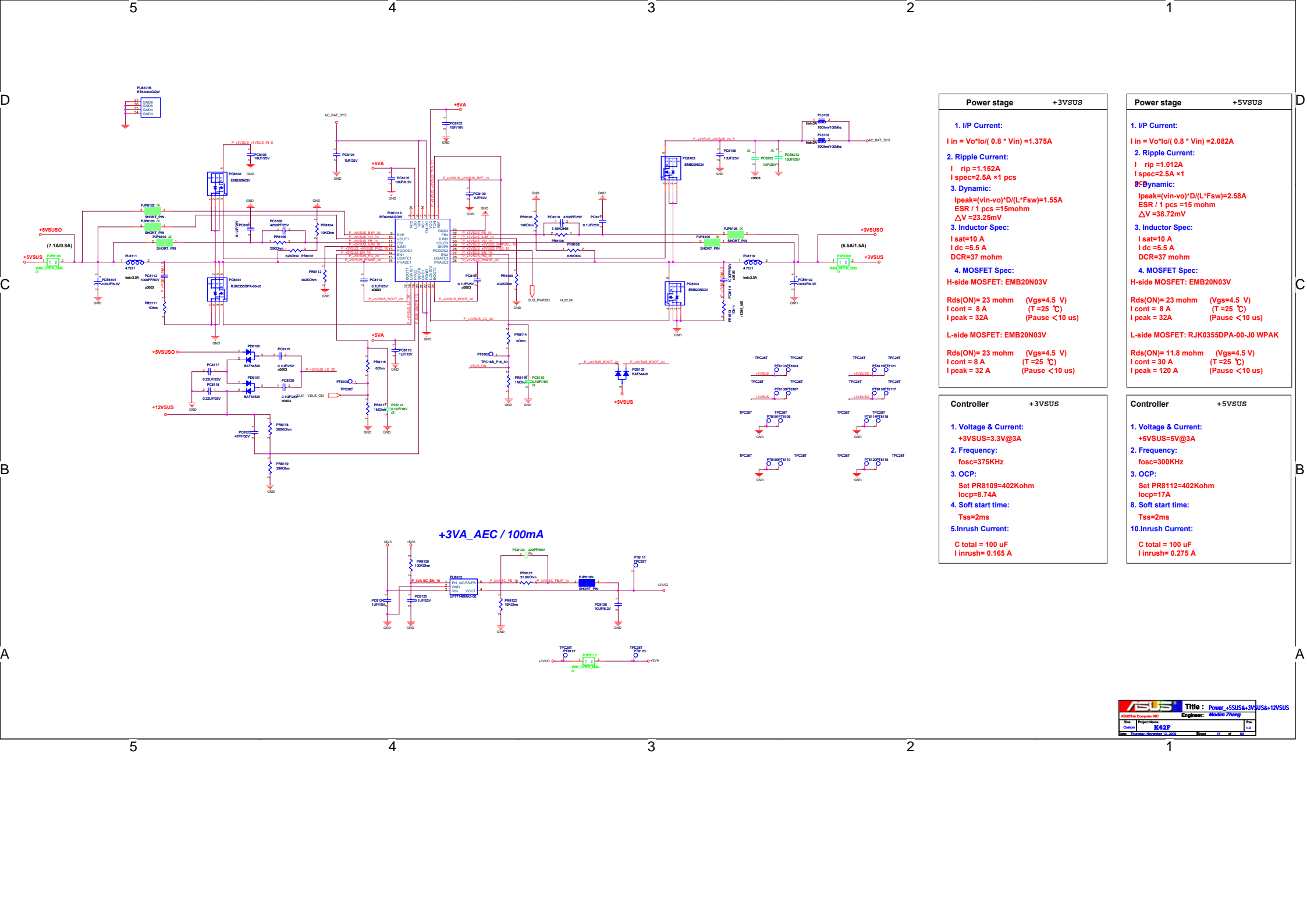
HDD 呼吸孔







STD version :1.1g(09/08/21)

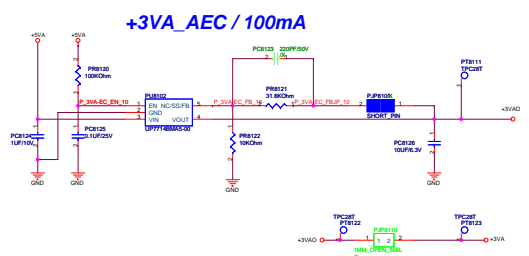


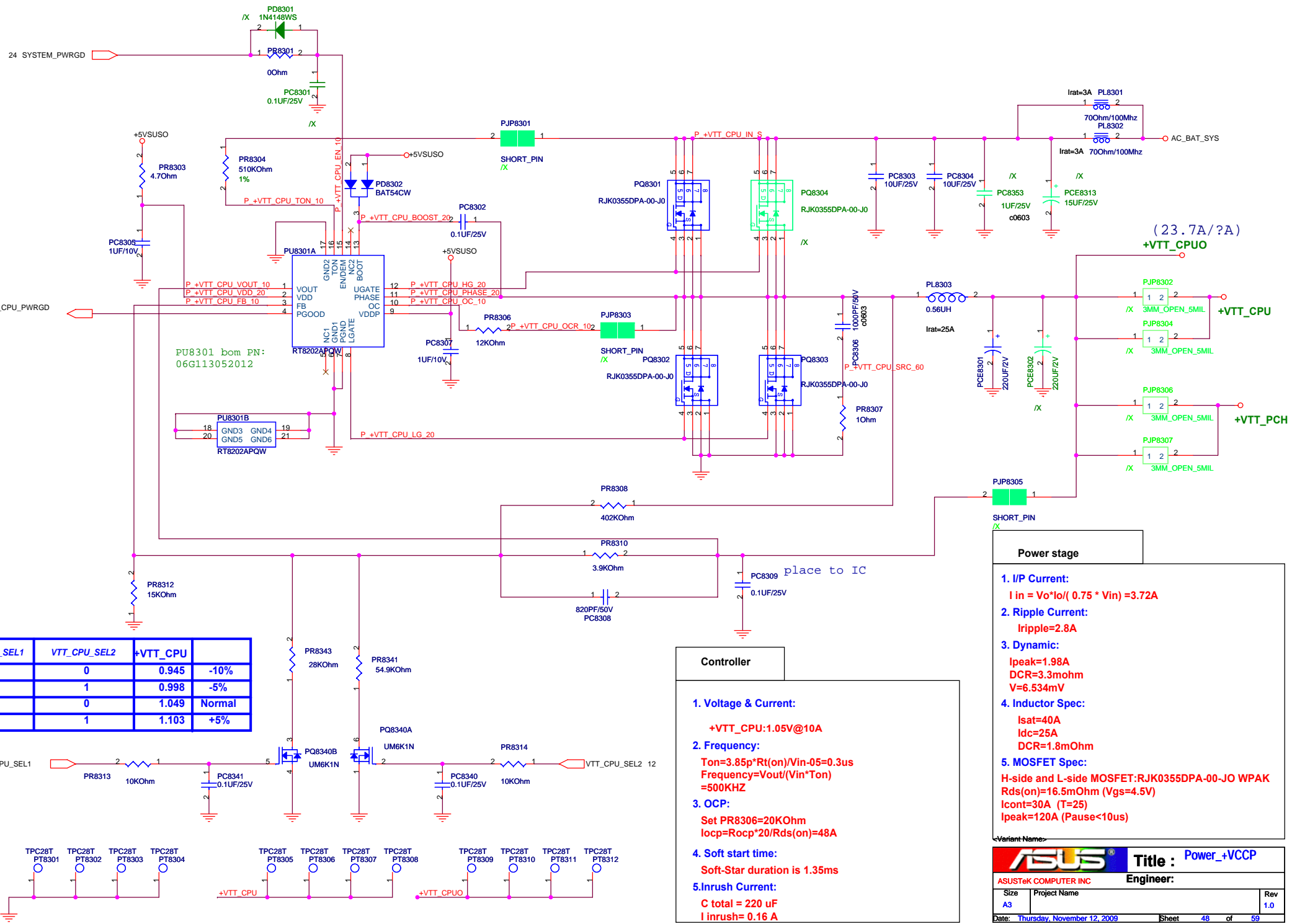
Power stage		+3VSUS
1. I/P Current:		
$I_{in} = V_o \cdot I_o / (0.8 \cdot V_{in}) = 1.375A$		
2. Ripple Current:		
$I_{rip} = 1.152A$		
$I_{spec} = 2.5A \times 1 \text{ pcs}$		
3. Dynamic:		
$I_{peak} = (v_{in} - v_o) \cdot D / (L \cdot F_{sw}) = 1.55A$		
ESR / 1 pcs = 15mohm		
$\Delta V = 23.25mV$		
3. Inductor Spec:		
$I_{sat} = 10A$		
$I_{dc} = 5.5A$		
DCR = 37 mohm		
4. MOSFET Spec:		
H-side MOSFET: EMB20N03V		
Rds(ON) = 23 mohm (Vgs=4.5 V)		
I cont = 8 A (T = 25 °C)		
I peak = 32 A (Pause < 10 us)		
L-side MOSFET: EMB20N03V		
Rds(ON) = 23 mohm (Vgs=4.5 V)		
I cont = 8 A (T = 25 °C)		
I peak = 32 A (Pause < 10 us)		

Power stage		+5VSUS
1. I/P Current:		
$I_{in} = V_o \cdot I_o / (0.8 \cdot V_{in}) = 2.082A$		
2. Ripple Current:		
$I_{rip} = 1.012A$		
$I_{spec} = 2.5A \times 1 \text{ pcs}$		
3. Dynamic:		
$I_{peak} = (v_{in} - v_o) \cdot D / (L \cdot F_{sw}) = 2.58A$		
ESR / 1 pcs = 15 mohm		
$\Delta V = 38.72mV$		
3. Inductor Spec:		
$I_{sat} = 10A$		
$I_{dc} = 5.5A$		
DCR = 37 mohm		
4. MOSFET Spec:		
H-side MOSFET: EMB20N03V		
Rds(ON) = 23 mohm (Vgs=4.5 V)		
I cont = 8 A (T = 25 °C)		
I peak = 32 A (Pause < 10 us)		
L-side MOSFET: RJK0355DPA-00-J0 WPAK		
Rds(ON) = 11.8 mohm (Vgs=4.5 V)		
I cont = 30 A (T = 25 °C)		
I peak = 120 A (Pause < 10 us)		

Controller		+3VSUS
1. Voltage & Current:		
+3VSUS = 3.3V@3A		
2. Frequency:		
fosc = 375KHz		
3. OCP:		
Set PR8109 = 402Kohm		
Iocp = 8.74A		
4. Soft start time:		
Tss = 2ms		
5. Inrush Current:		
C total = 100 uF		
I inrush = 0.165 A		

Controller		+5VSUS
1. Voltage & Current:		
+5VSUS = 5V@3A		
2. Frequency:		
fosc = 300KHz		
3. OCP:		
Set PR8112 = 402Kohm		
Iocp = 17A		
8. Soft start time:		
Tss = 2ms		
10. Inrush Current:		
C total = 100 uF		
I inrush = 0.275 A		





PU8301 bom PN:
06G113052012

PU8301B
RT8202APQW

VTT_CPU_SEL1	VTT_CPU_SEL2	+VTT_CPU	
0	0	0.945	-10%
0	1	0.998	-5%
1	0	1.049	Normal
1	1	1.103	+5%

Controller

- Voltage & Current:**
+VTT_CPU: 1.05V@10A
- Frequency:**
Ton=3.85p*Rt(on)/Vin-0.5=0.3us
Frequency=Vout/(Vin*Ton)=500KHZ
- OCP:**
Set PR8306=20Kohm
Iocp=Rocp*20/Rds(on)=48A
- Soft start time:**
Soft-Star duration is 1.35ms
- Inrush Current:**
C total = 220 uF
I inrush= 0.16 A

Power stage

- I/P Current:**
I in = Vo*Io/(0.75 * Vin) = 3.72A
- Ripple Current:**
Iripple=2.8A
- Dynamic:**
Ipeak=1.98A
DCR=3.3mohm
V=6.534mV
- Inductor Spec:**
Isat=40A
Idc=25A
DCR=1.8mOhm
- MOSFET Spec:**
H-side and L-side MOSFET:RJK0355DPA-00-JO WPAK
Rds(on)=16.5mOhm (Vgs=4.5V)
Icont=30A (T=25)
Ipeak=120A (Pause<10us)

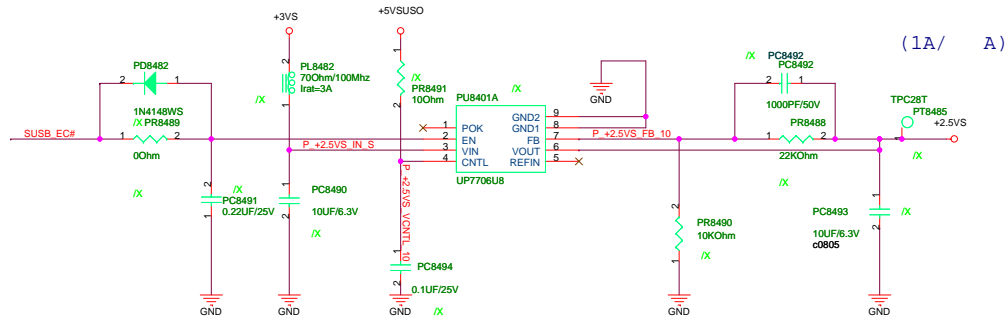
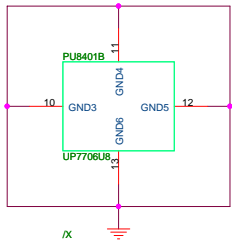
Variant Name: _____

ASUS Title : Power_VCCP

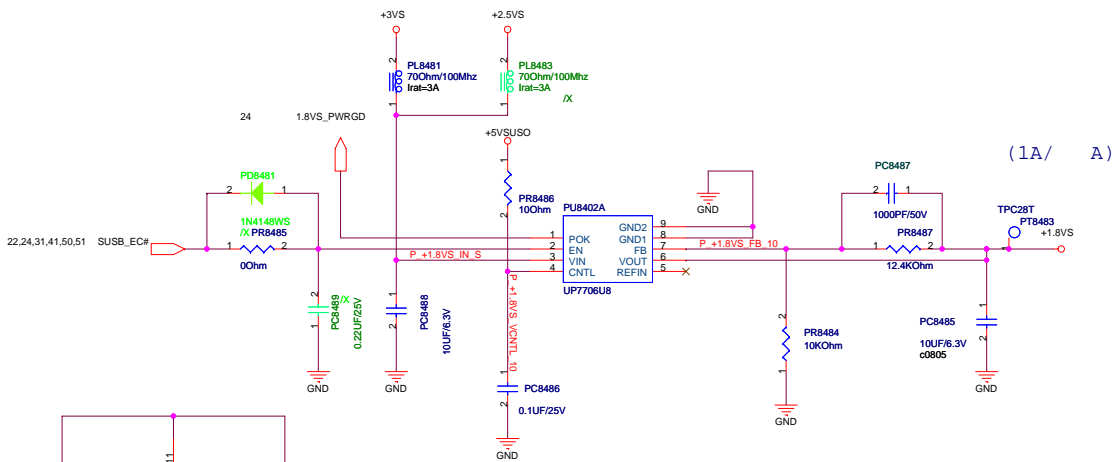
ASUSTeK COMPUTER INC Engineer:

Size	Project Name	Rev
A3		1.0

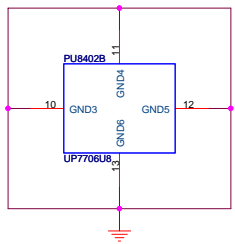
Date: Thursday, November 12, 2009 Sheet 48 of 59



(1A/ A)



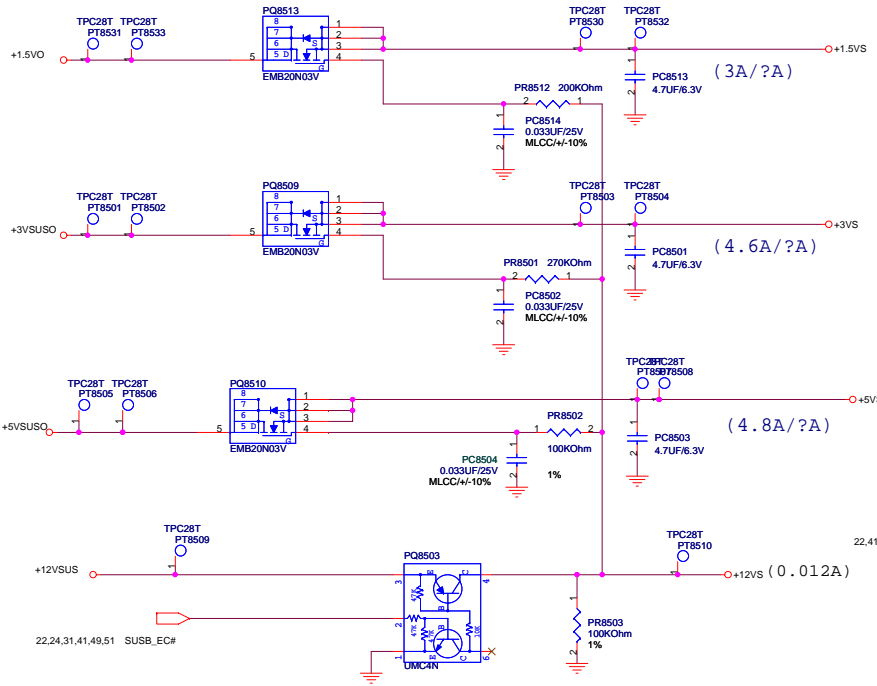
(1A/ A)



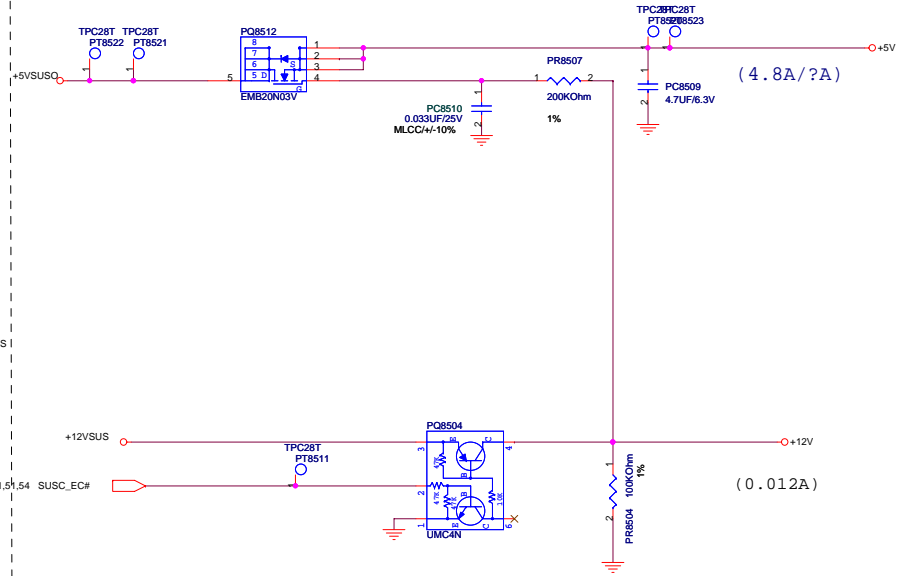
<Variant Name>

ASUS		Title : Power_+1.8V&+0.9V
ASUSTeK COMPUTER INC		Engineer:
Size	Project Name	Rev
Custom		1.0
Date: Thursday, November 12, 2009	Sheet 49 of 59	

SUSB#_PWR POWER

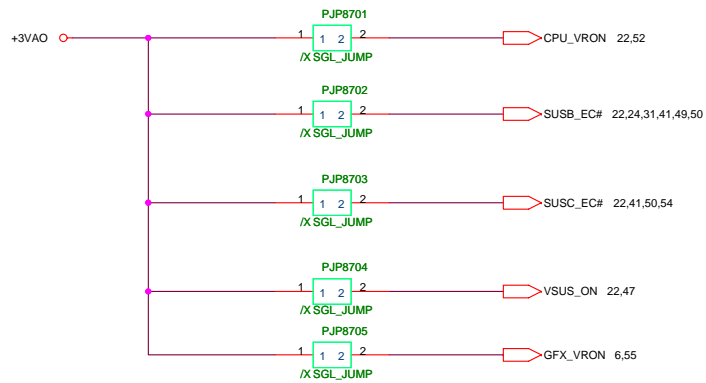


SUSC#_PWR POWER




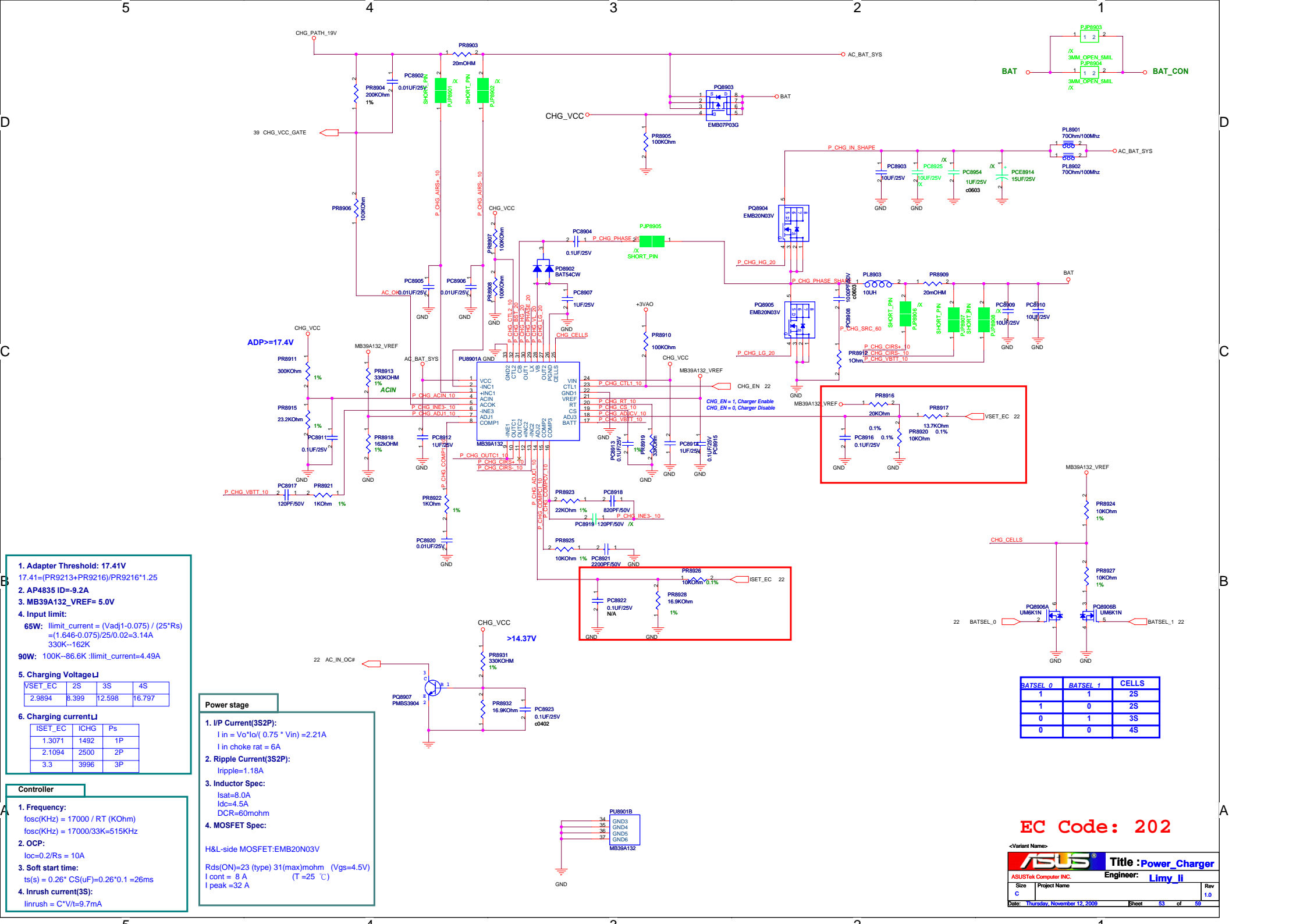
<Variant Name>

ASUS		Title : Power_Load_Switch
ASUSTek COMPUTER INC		Engineer:
Size	Project Name	Rev
Custom		1.0
Date: Thursday, November 12, 2009	Sheet 50 of 59	



<Variant Name>

		Title :Power_for_test
ASUSTeK COMPUTER INC		Engineer:
Size	Project Name	Rev
Custom		1.0
Date: Thursday, November 12, 2009	Sheet	51 of 59



- 1. Adapter Threshold: 17.41V**
 $17.41 = (PR9213 + PR9216) / PR9216 * 1.25$
- 2. AP4835 ID=9.2A**
- 3. MB39A132_VREF= 5.0V**
- 4. Input limit:**
65W: $I_{limit_current} = (V_{adj} - 0.075) / (25 * R_s) = (1.646 - 0.075) / 25 / 0.02 = 3.14A$
 330K-162K
90W: 100K-86.6K : $I_{limit_current} = 4.49A$

5. Charging VoltageLI

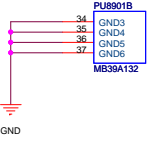
VSET_EC	2S	3S	4S
2.9894	3.399	12.598	16.797

6. Charging currentLI

ISET_EC	ICHG	Ps
1.3071	1492	1P
2.1094	2500	2P
3.3	3996	3P

- Controller**
- 1. Frequency:**
 $f_{osc}(KHz) = 17000 / RT (KOhm)$
 $f_{osc}(KHz) = 17000 / 33K = 515KHz$
 - 2. OCP:**
 $I_{oc} = 0.2 / R_s = 10A$
 - 3. Soft start time:**
 $t_s(s) = 0.26 * CS(uF) = 0.26 * 0.1 = 26ms$
 - 4. Inrush current(3S):**
 $I_{inrush} = C * V / t = 9.7mA$

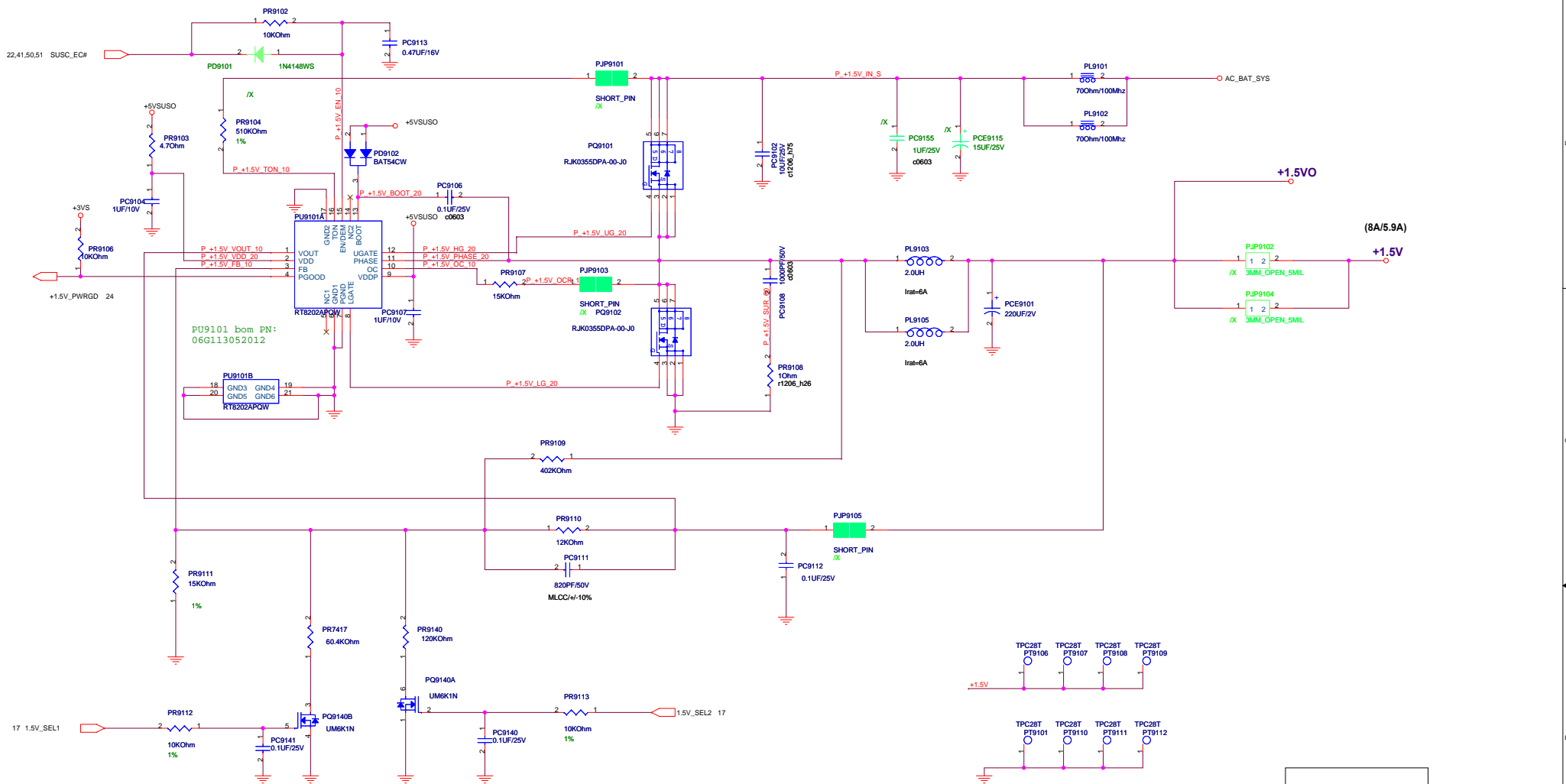
- Power stage**
- 1. I/P Current(3S2P):**
 $I_{in} = V_o * I_o / (0.75 * V_{in}) = 2.21A$
 I_{in} choke rat = 6A
 - 2. Ripple Current(3S2P):**
 $I_{ripple} = 1.18A$
 - 3. Inductor Spec:**
 $I_{sat} = 8.0A$
 $I_{dc} = 4.5A$
 $DCR = 60mohm$
 - 4. MOSFET Spec:**
 H&L-side MOSFET: EMB20N03V
 $R_{ds}(ON) = 23$ (type) 31 (max) $mohm$ ($V_{gs} = 4.5V$)
 $I_{cont} = 8A$ ($T = 25^\circ C$)
 $I_{peak} = 32A$



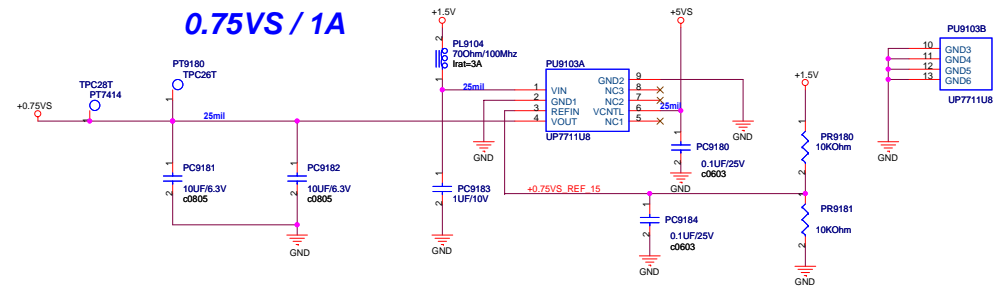
EC Code: 202

<Variant Names>

ASUS		Title : Power Charger
ASUSTek Computer INC.		Engineer: Limy Ji
Size	Project Name	Rev
C		1.0
Date: Thursday, November 12, 2009		Sheet 53 of 59



0.75VS / 1A



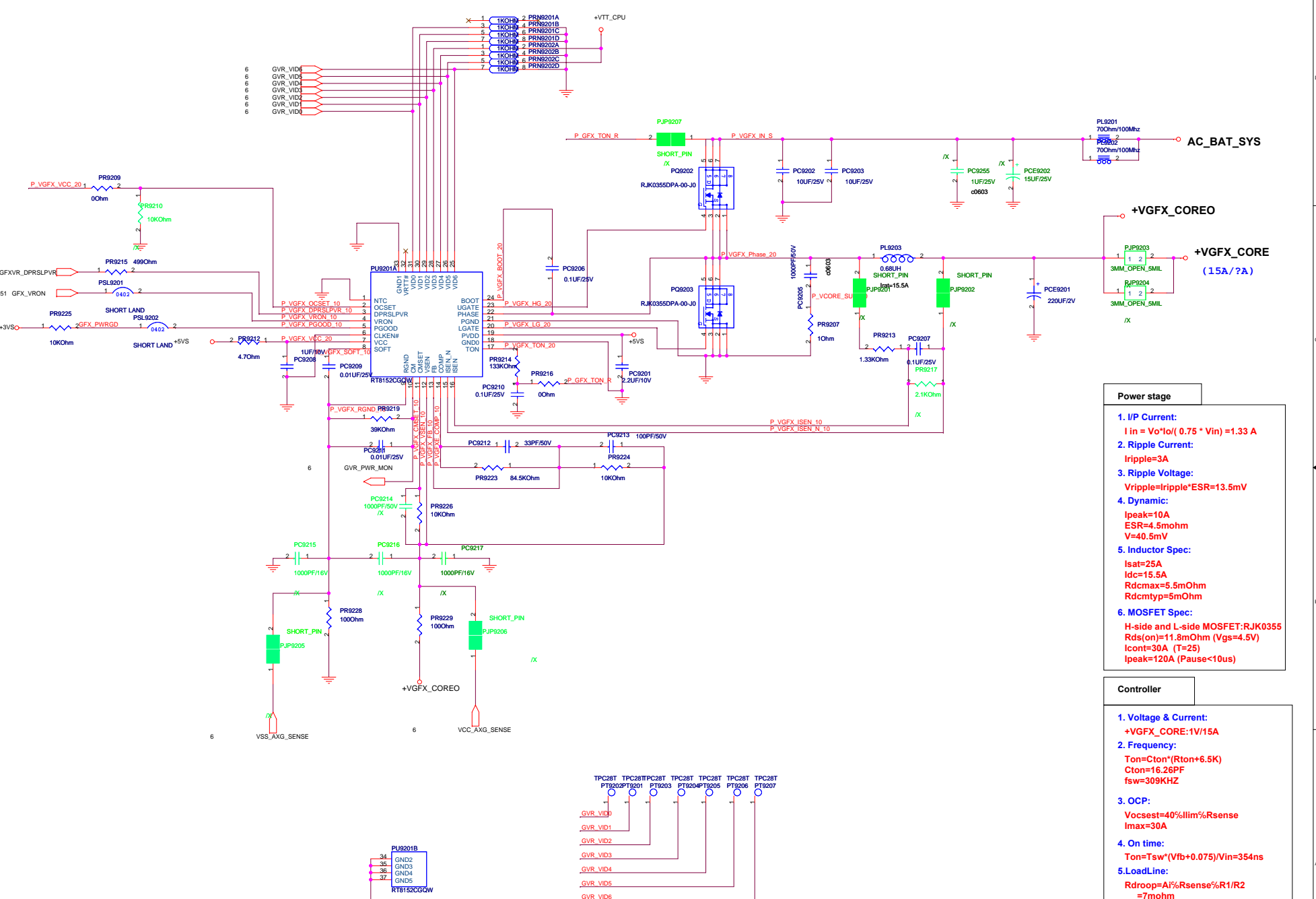
1.5V_SEL1	1.5V_SEL2	+1.5V	
0	0	1.35	-10%
0	1	1.425	-5%
1	0	1.5	Normal
1	1	1.575	+5%

Controller

- Voltage & Current:**
1.5V: 8A
- Frequency:**
Ton=3.85p*RT(on)/Vin-05=0.3us
Frequency=Vout/(Vin*Ton)=500KHZ
- OCPC:**
Set PR9107=20kohm
Iocp=Rocp*20/Rds(on)=24A
- Soft start time:**
Soft-Star duration is 1.35ms
- Inrush Current:**
C total =220uF
I inrush=0.163A

Power stage

- I/P Current:**
I in = Vo*Io/(0.75 * Vin) =1.33A
- Ripple Current:**
Iripple=3.74A
- ripple voltage:**
Ipeak=(vin-vo)*D/(L*Fsw)=2.07A
DCR=3.3mohm
V=6.831mV
- Inductor Spec:**
Isat=22A
Idc=11A
DCR=10mohm
- MOSFET Spec:**
H-side and L-side MOSFET:
Rds(on)=16.5mOhm (Vgs=4.5V)
Icont=30A (T=25)
Ipeak=120A (Pause<10us)



Power stage

- I/P Current:**
 $I_{in} = V_o / I_o (0.75 * V_{in}) = 1.33 A$
- Ripple Current:**
 $I_{ripple} = 3A$
- Ripple Voltage:**
 $V_{ripple} = I_{ripple} * ESR = 13.5mV$
- Dynamic:**
 $I_{peak} = 10A$
 $ESR = 4.5mohm$
 $V = 40.5mV$
- Inductor Spec:**
 $I_{sat} = 25A$
 $I_{dc} = 15.5A$
 $R_{dcmax} = 5.5mOhm$
 $R_{dc} = 5mOhm$
- MOSFET Spec:**
 H-side and L-side MOSFET: RJK0355
 $R_{ds(on)} = 11.8mOhm (V_{gs} = 4.5V)$
 $I_{cont} = 30A (T = 25)$
 $I_{peak} = 120A (Pause < 10us)$

Controller

- Voltage & Current:**
 $+VGTX_CORE: 1V/15A$
- Frequency:**
 $Ton = C_{ton} * (R_{ton} + 6.5K)$
 $C_{ton} = 16.26PF$
 $f_{sw} = 309KHZ$
- OCP:**
 $V_{ocst} = 40% I_{lim} * R_{sense}$
 $I_{max} = 30A$
- On time:**
 $Ton = T_{sw} * (V_{fb} + 0.075) / V_{in} = 354ns$
- Load Line:**
 $R_{droop} = A * I * R_{sense} * R1 / R2$
 $= 7mohm$

VTT_CPU_SEL1 Default : H
 VTT_CPU_SEL2 Default : L

VTT_CPU_SEL1	VTT_CPU_SEL2	+VTT_CPU	
0	0	0.945	-10%
0	1	0.998	-5%
1	0	1.049	Normal
1	1	1.103	+5%

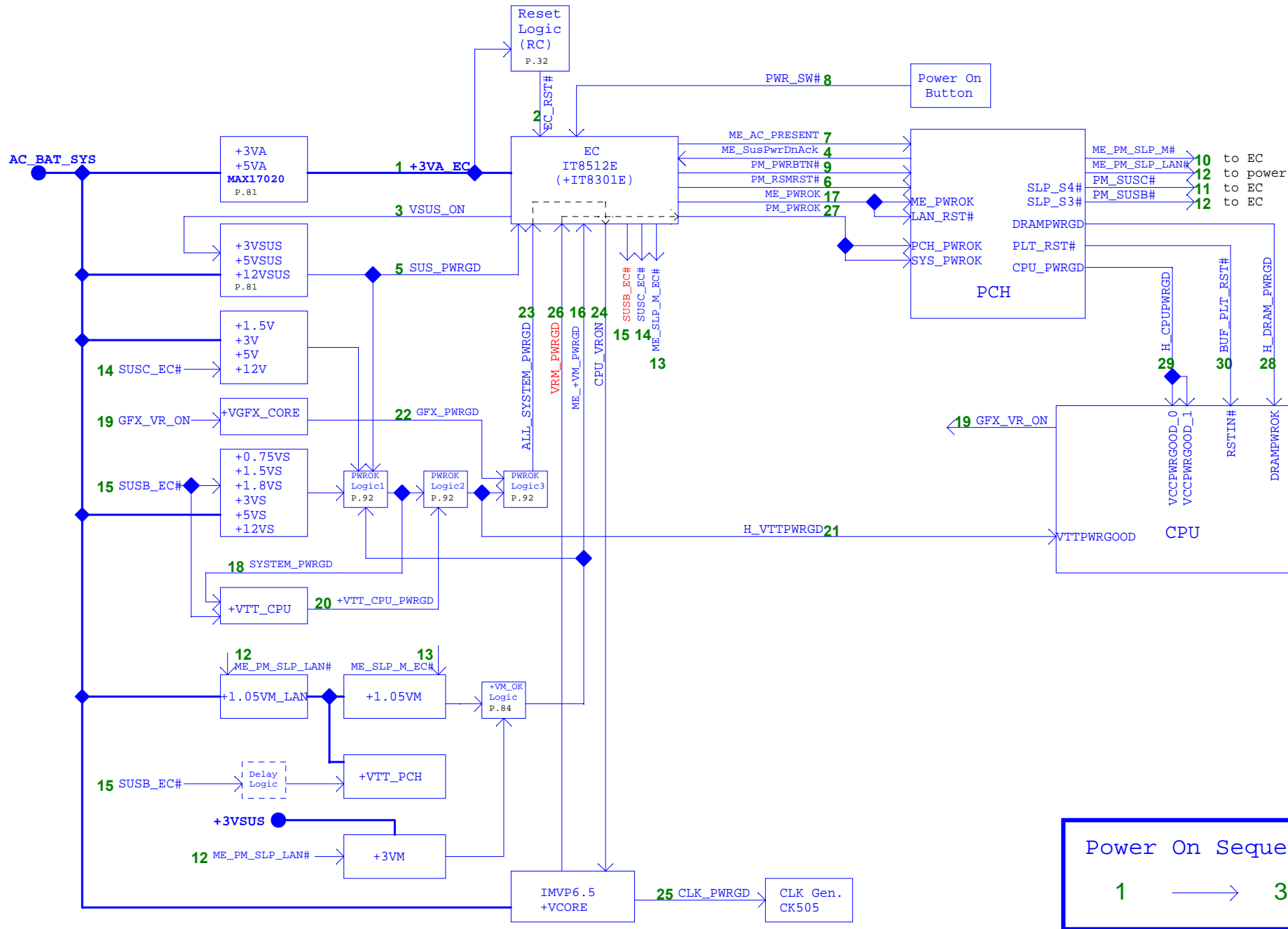
VCORE_SEL1 Default : H
 VCORE_SEL2 Default : L

VCORE_SEL1	VCORE_SEL2	+VCORE	
0	0	VID-100mV	-10%
0	1	VID-50mV	-5%
1	0	VID	Normal
1	1	VID+50mV	+5%

1.5V_SEL1 Default : H
 1.5V_SEL2 Default : L

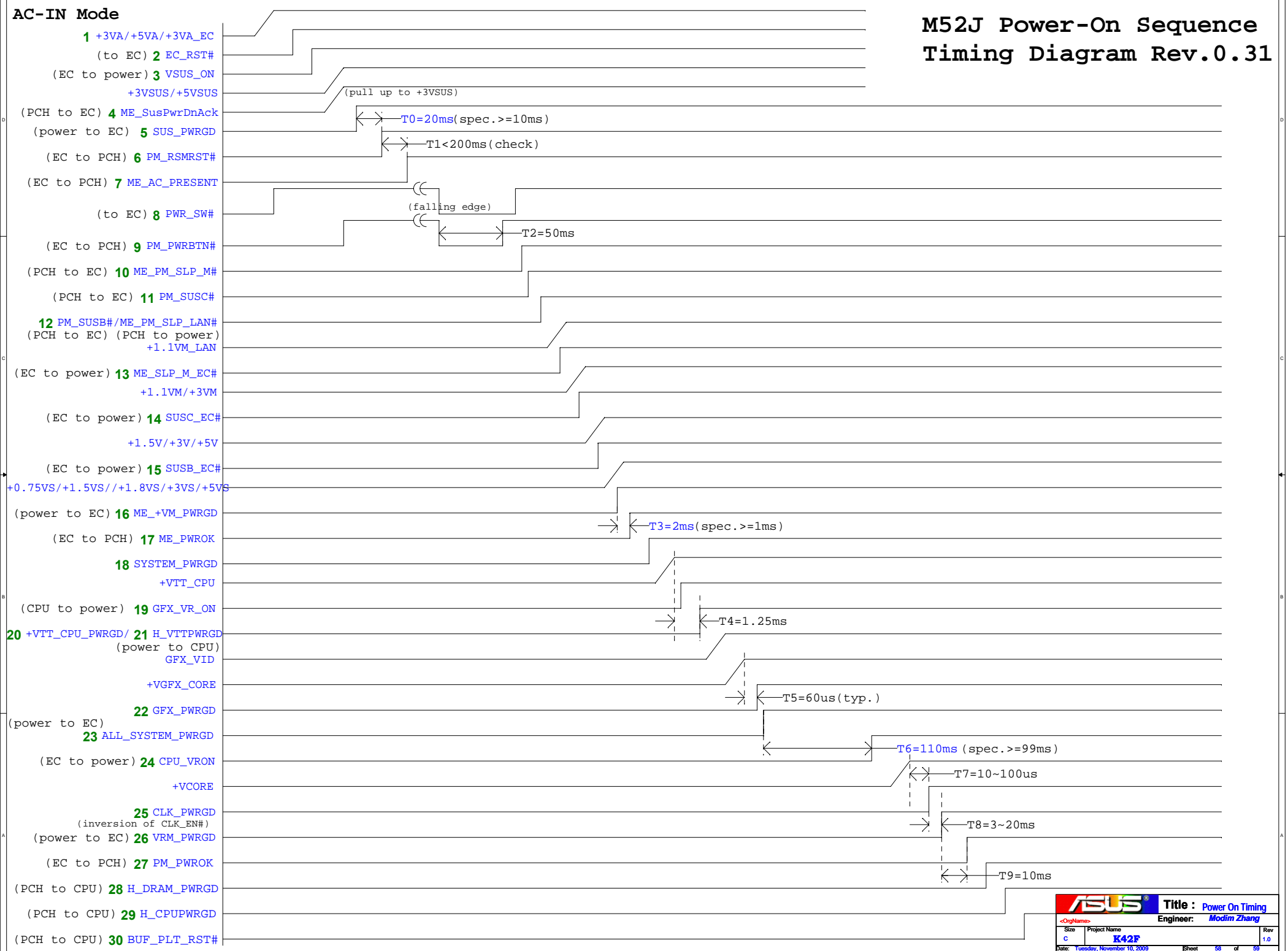
1.5V_SEL1	1.5V_SEL2	+1.5V	
0	0	1.35	-10%
0	1	1.425	-5%
1	0	1.5	Normal
1	1	1.575	+5%

<Variant Name>

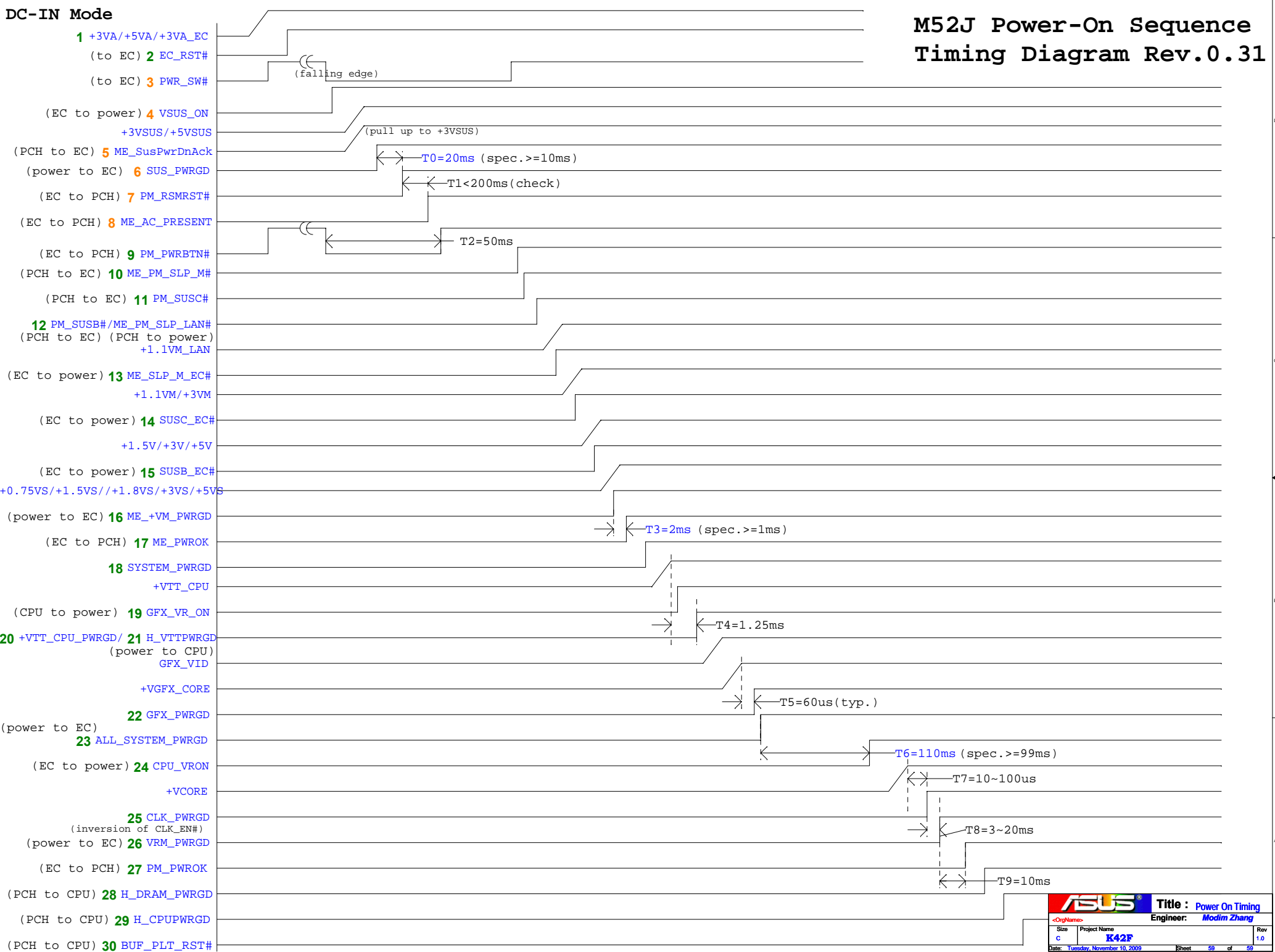


Power On Sequence
1 → 30

M52J Power-On Sequence Timing Diagram Rev.0.31



M52J Power-On Sequence Timing Diagram Rev.0.31



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